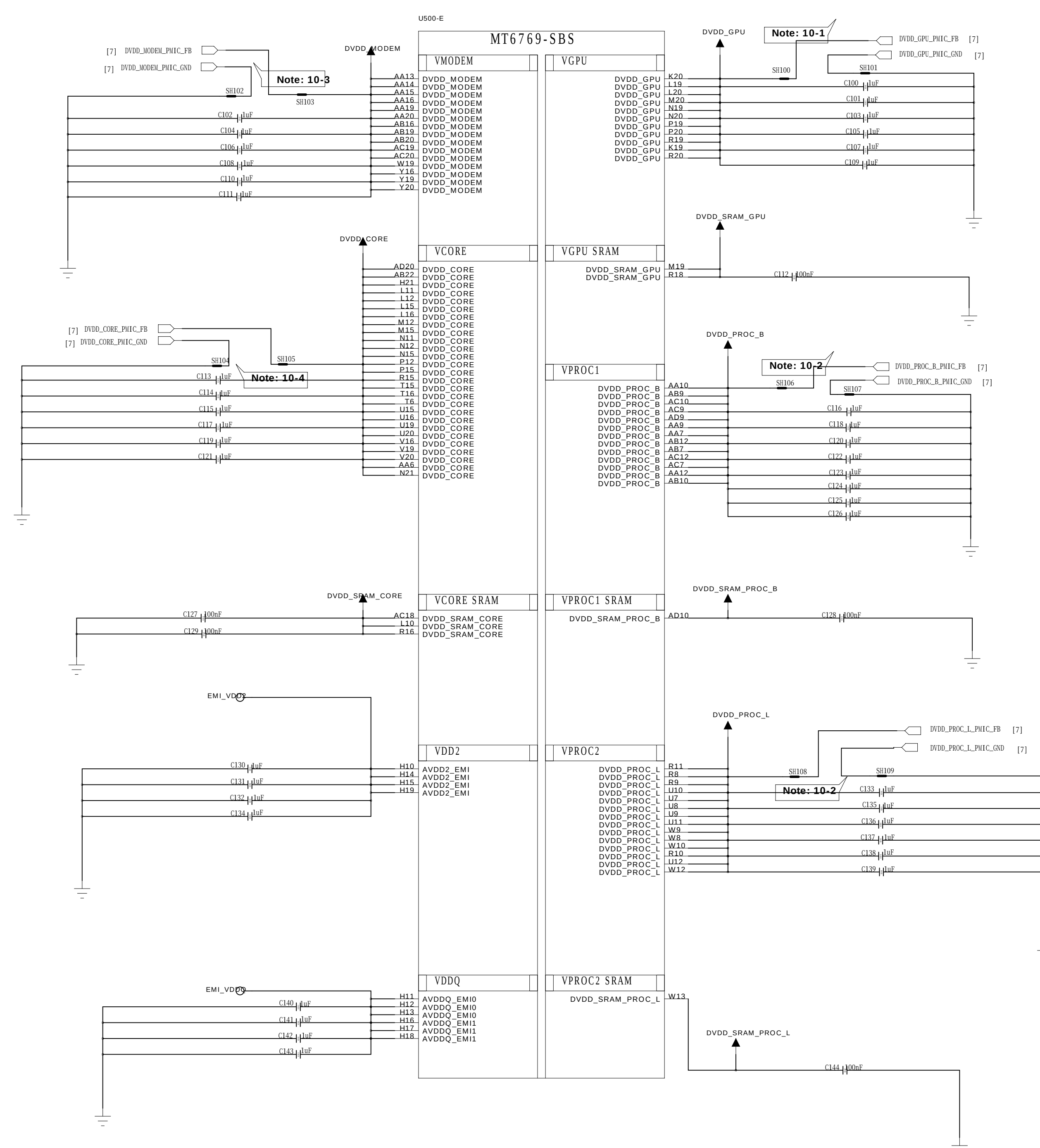




Schematic design notice of "10_BB_POWER_PDN" page:

Note 10-1: Differential pair of DVDD_GPU remote sense must be close to BB's pin pad.
Remote sense trace with GND shielding to PMIC (Differential)

Note 10-2: Differential pair of DVDD_PROC remote sense must be close trace with GND shielding to PMIC (Differential)

Note 10-3: Differential pair of DVDD_MODEM remote sense must be close to BB's rail. Remote sense rail with GND shielding to PMIC (Differential)

Note 10-4: Differential pair of DVDD_CORE remote sense must be close to PCB's rail
Remote sense rail with GND shielding to PMIC (Differential)

D

C

B

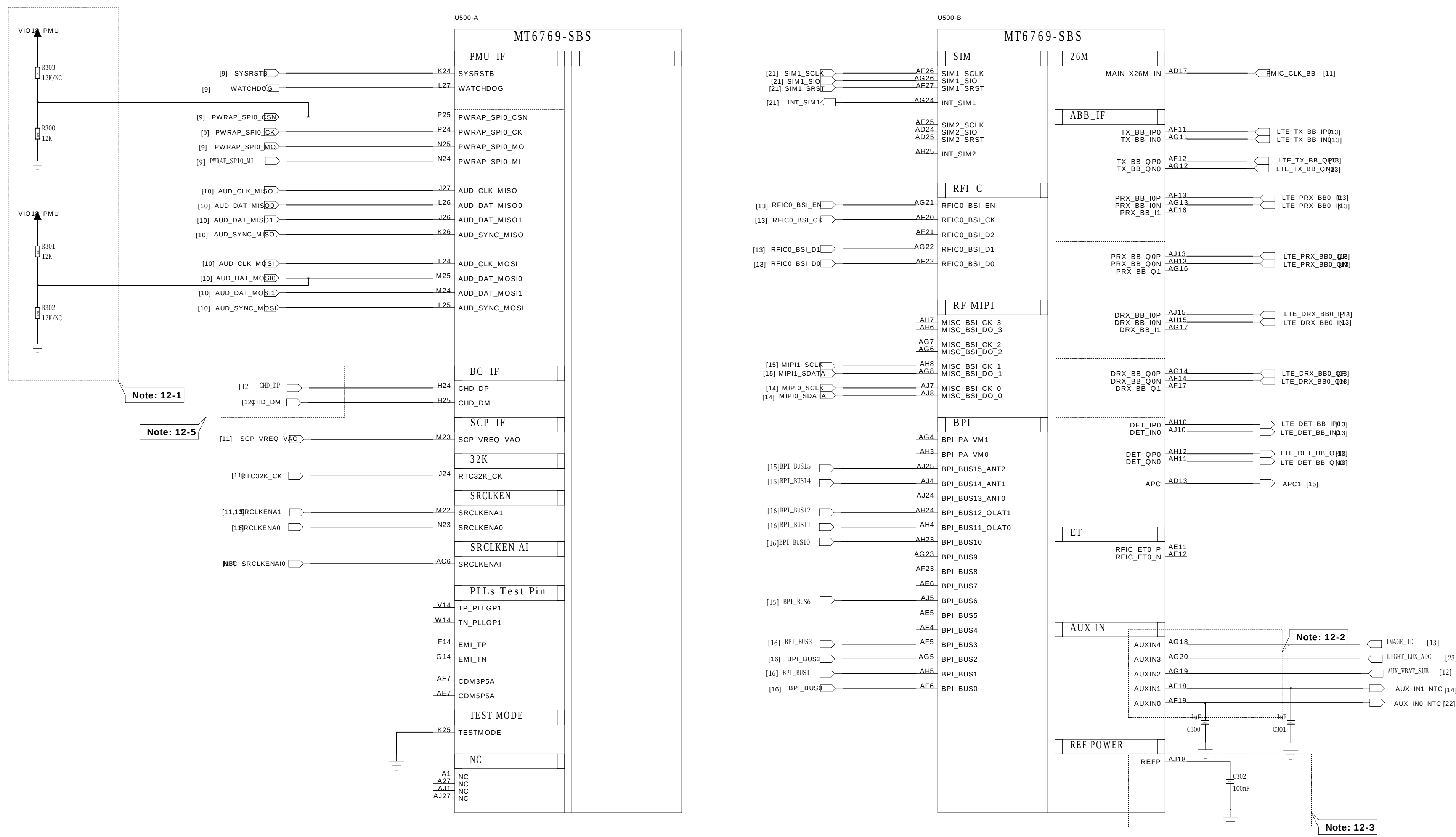
A

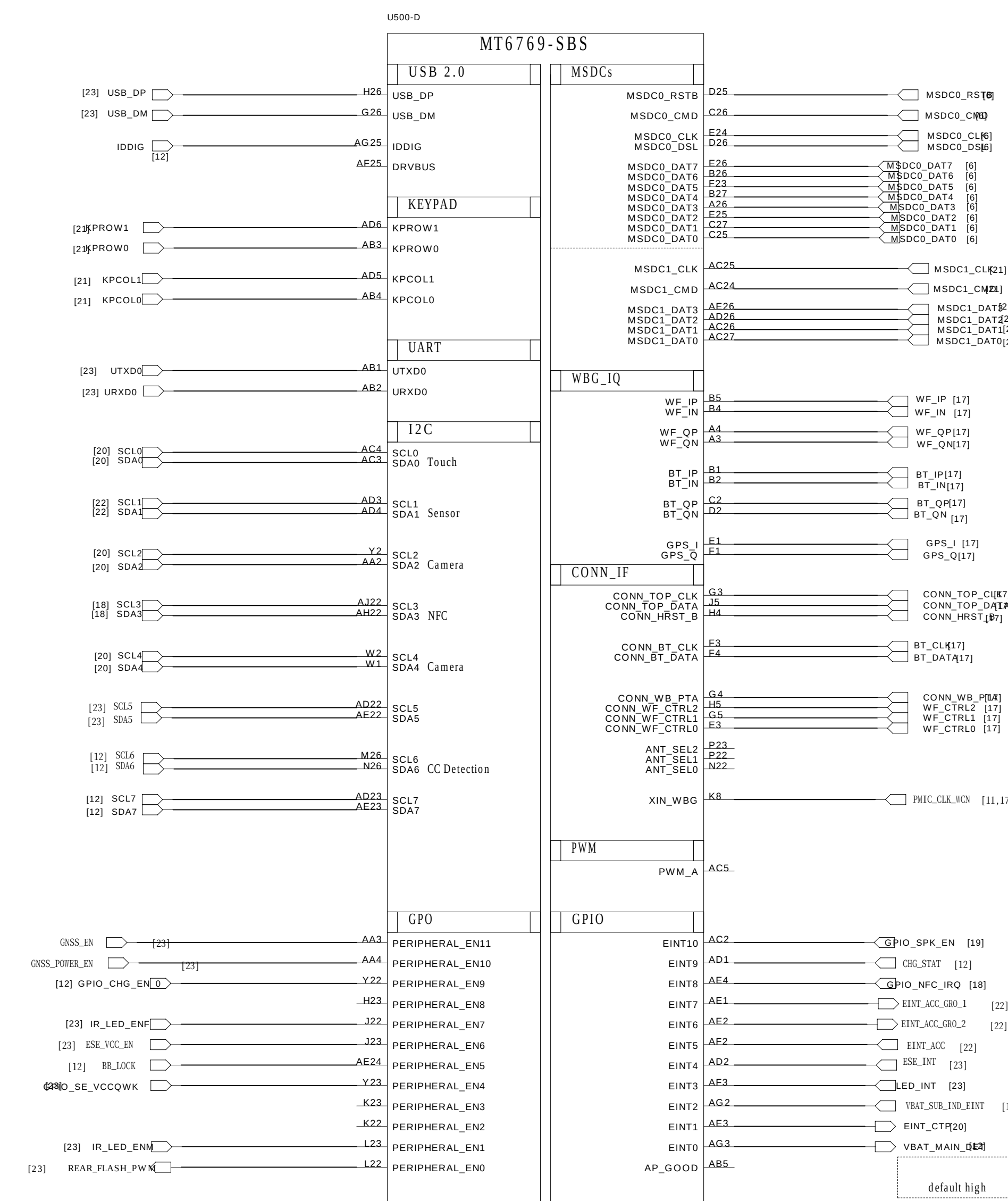
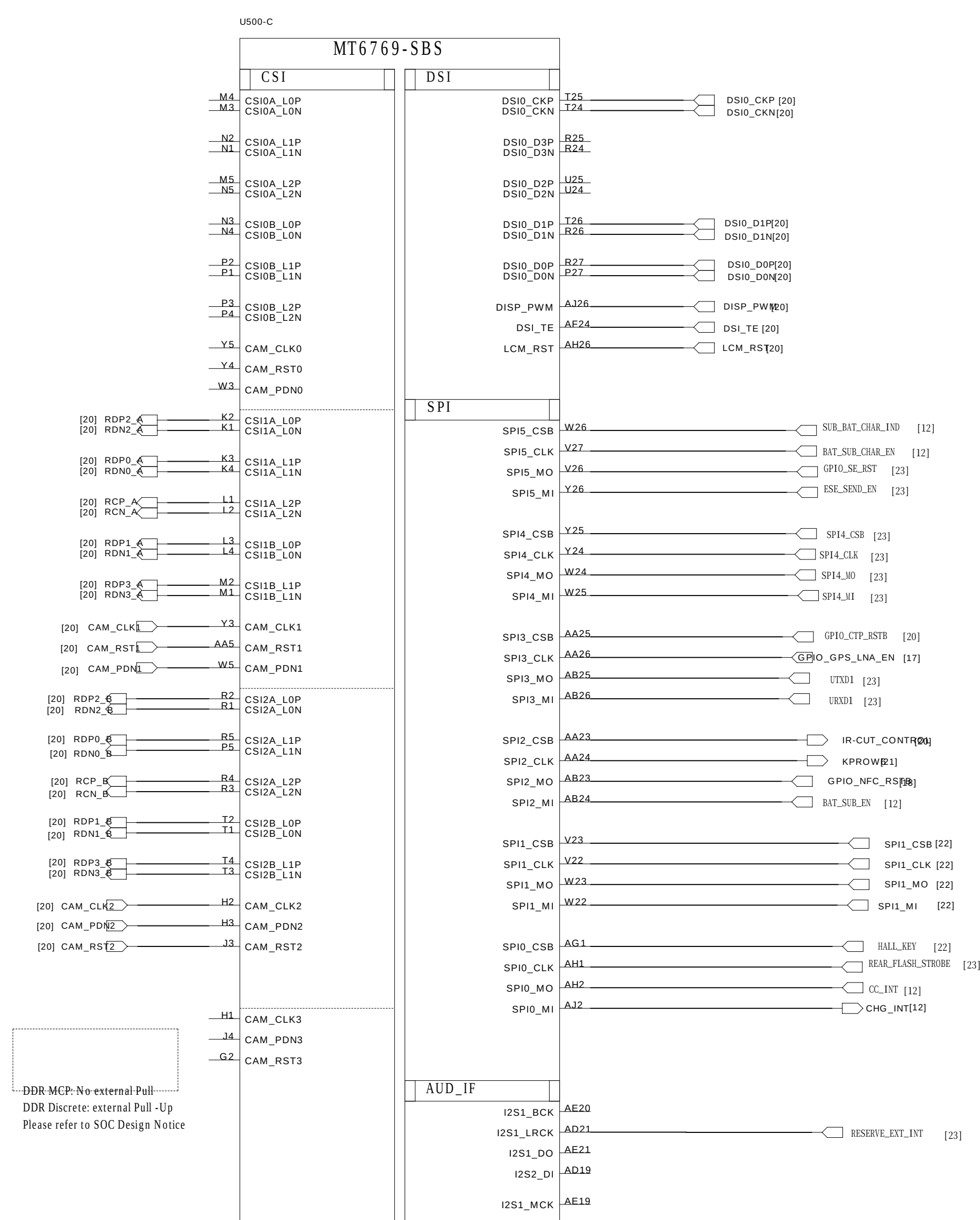
D

C

B

A





D

C

B

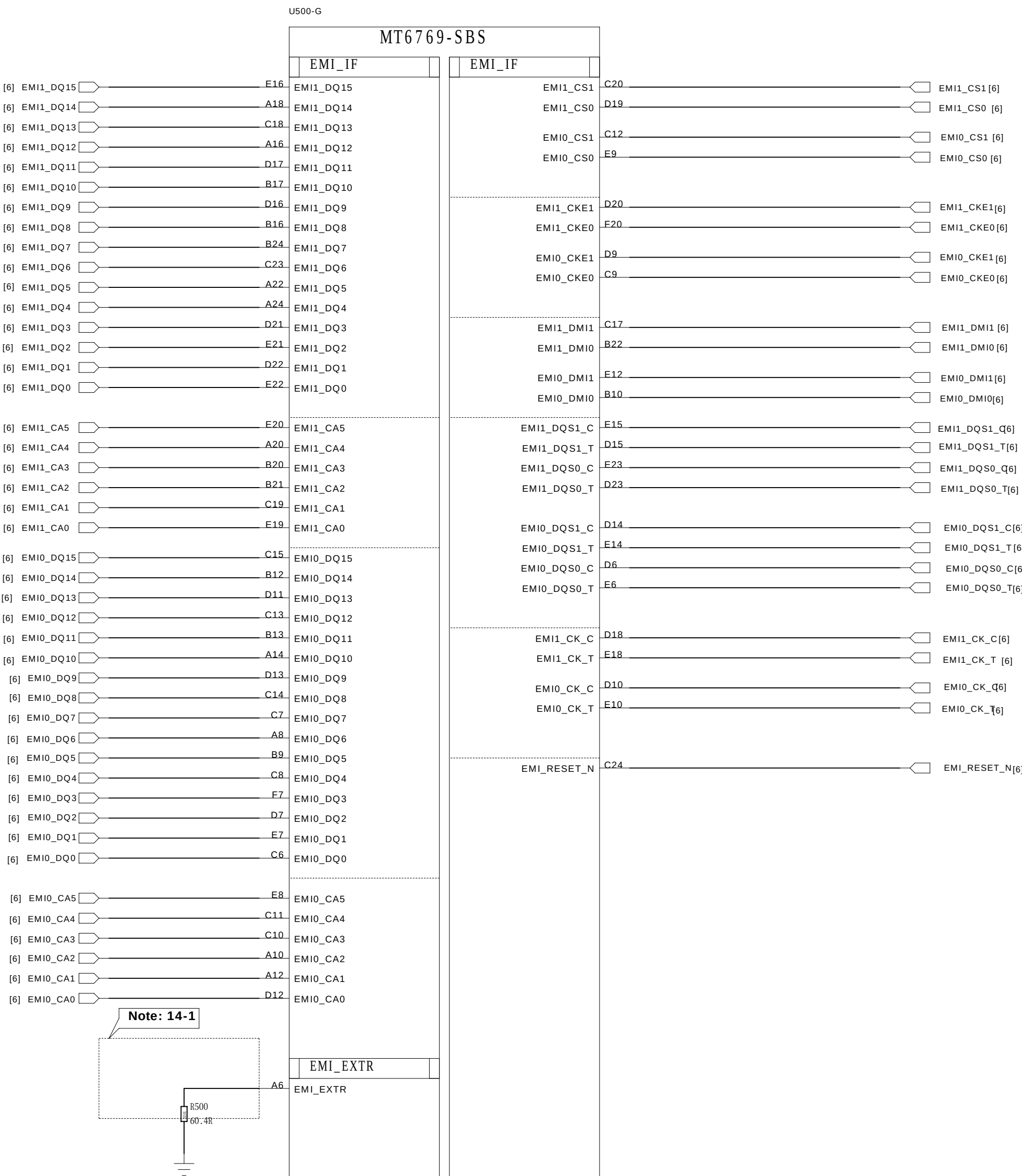
A

D

C

B

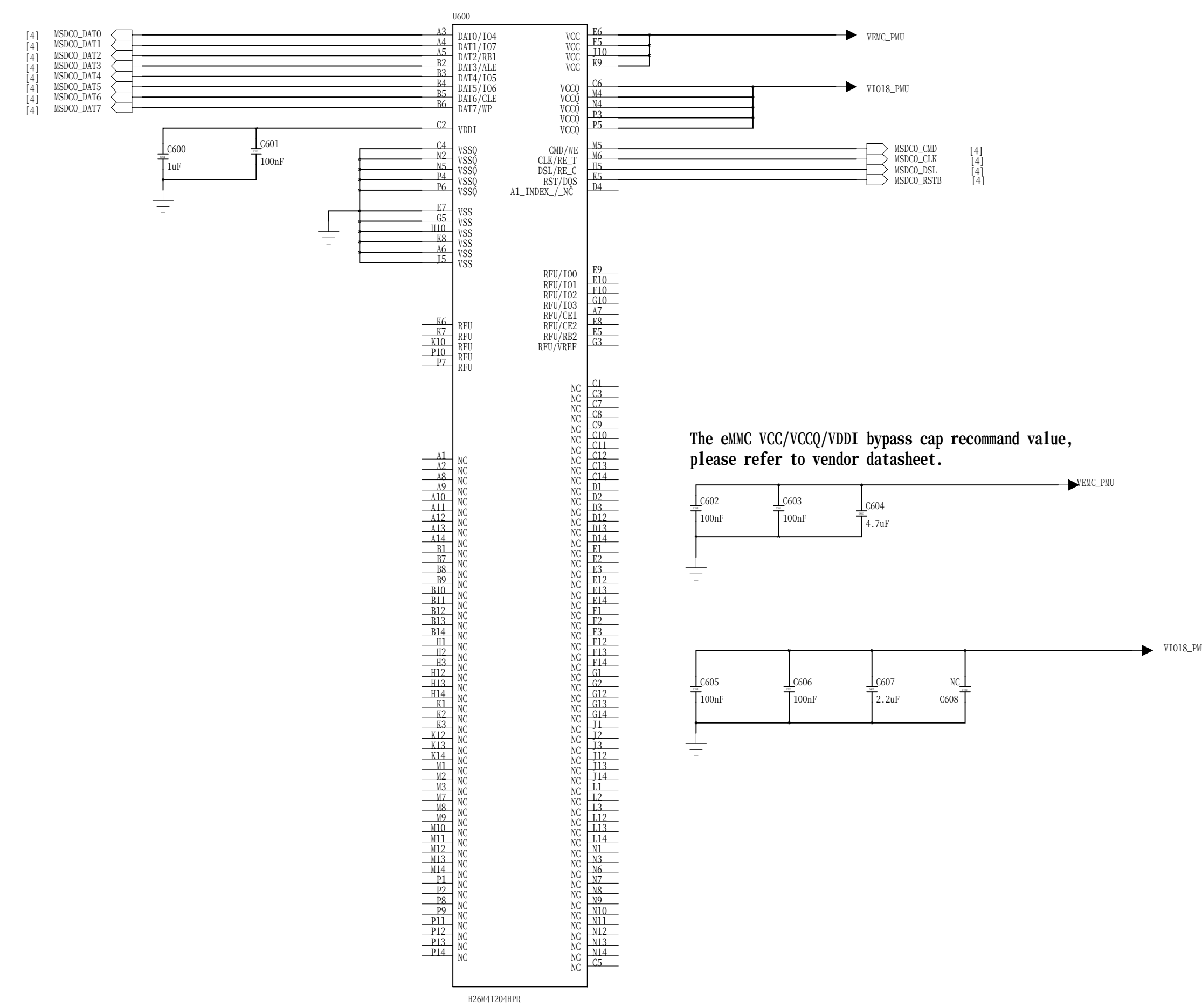
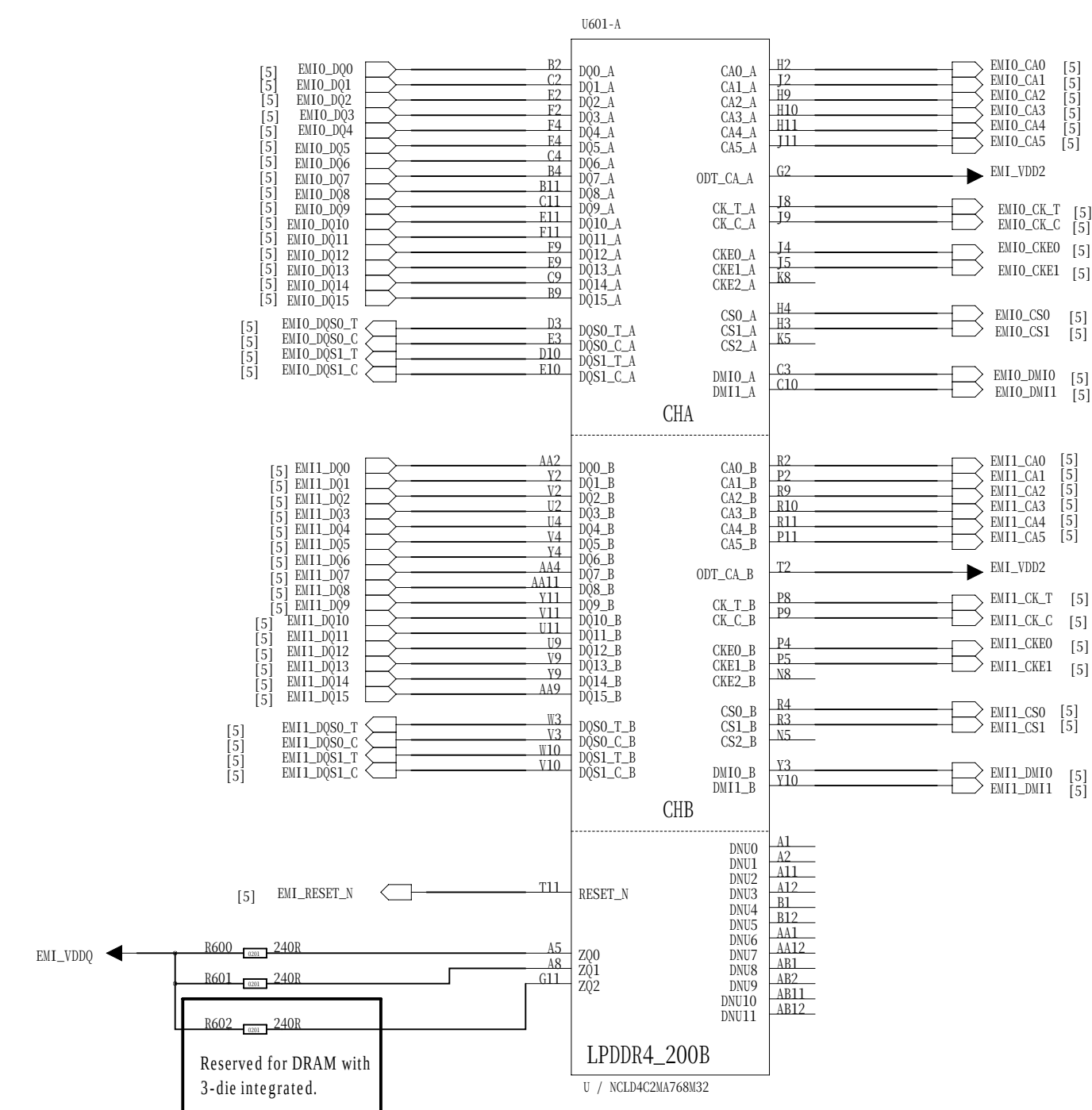
A



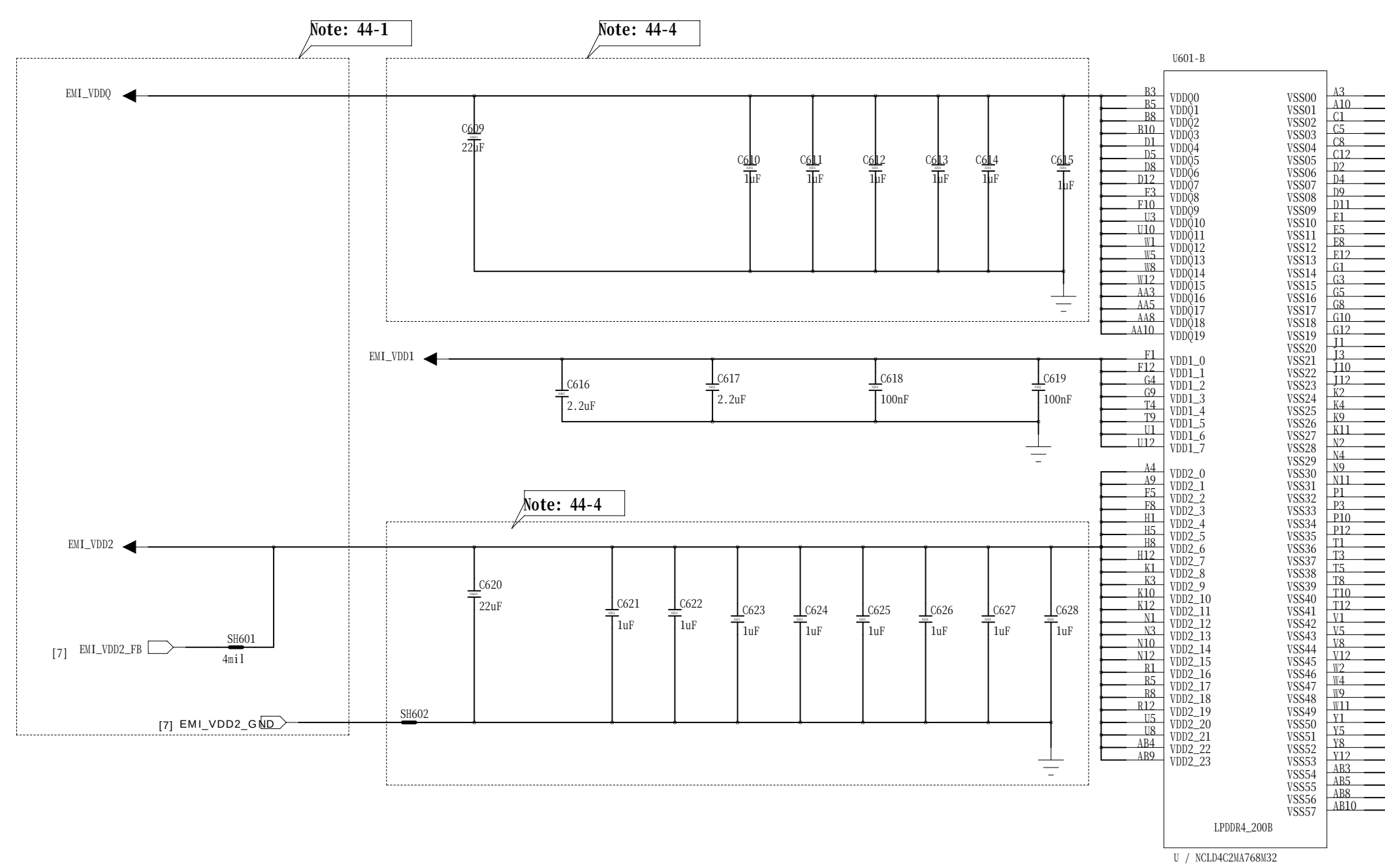
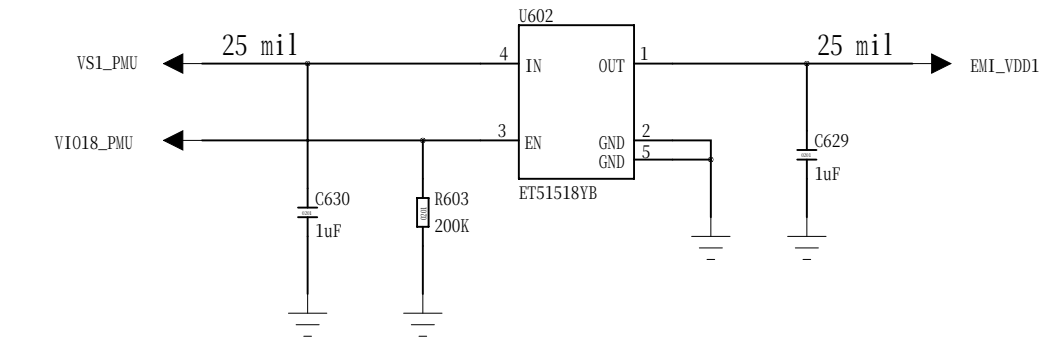
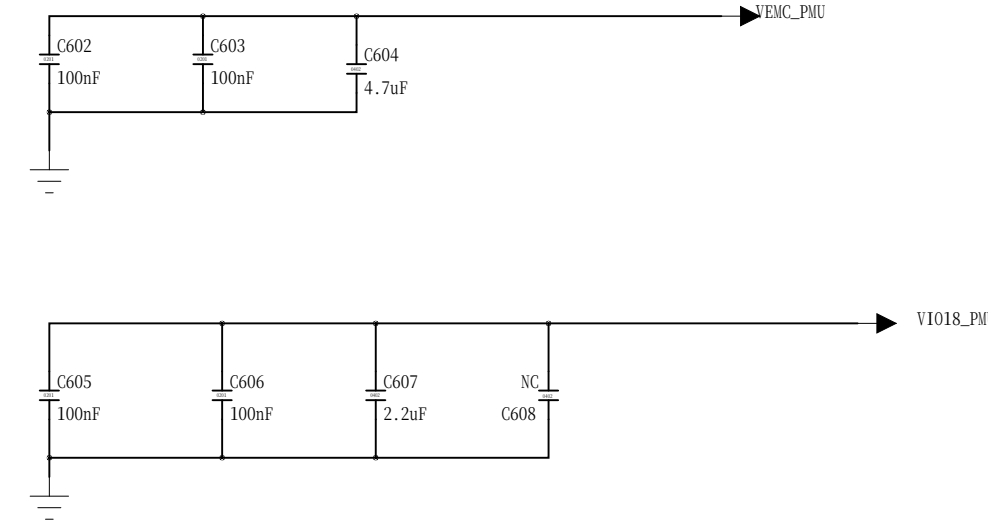
Schematic design notice of "14_BB_3" page.

Note 14-1: R4001 please select 60.4 ohm (1%) resistor

EMMC+LPDDR4X



The eMMC VCC/VCCQ/VDDI bypass cap recommend value, please refer to vendor datasheet.



Schematic design notice of "44_Memory_eMMC_LPDDR4"

Note 44-1: Please refer to power supply related page select output voltage properly for LPDDR4

Note 44-2: DRAM ZQx resistor = 240ohm (1%) that must be connected to VDDQ.

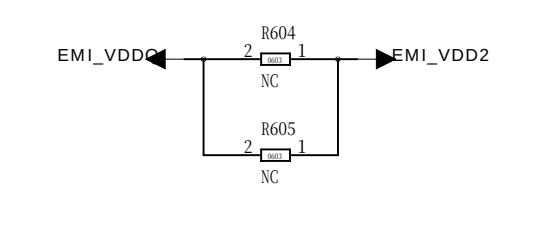
Note 44-4: VDD2 VDDQ decoupling cap: closed to DRAM ball.
For other cap for PMIC [>10uF, at PMIC page]:
please also refer to MMD and layout guide for placement.

Note 44-5:

DRAM type	R4437, R4438
LPDDR4	Mount
LPDDR4X	NC

Note: 44-5

Reserved for LP4 DRAM [VDDQ=1.1V]



预留

D

C

B

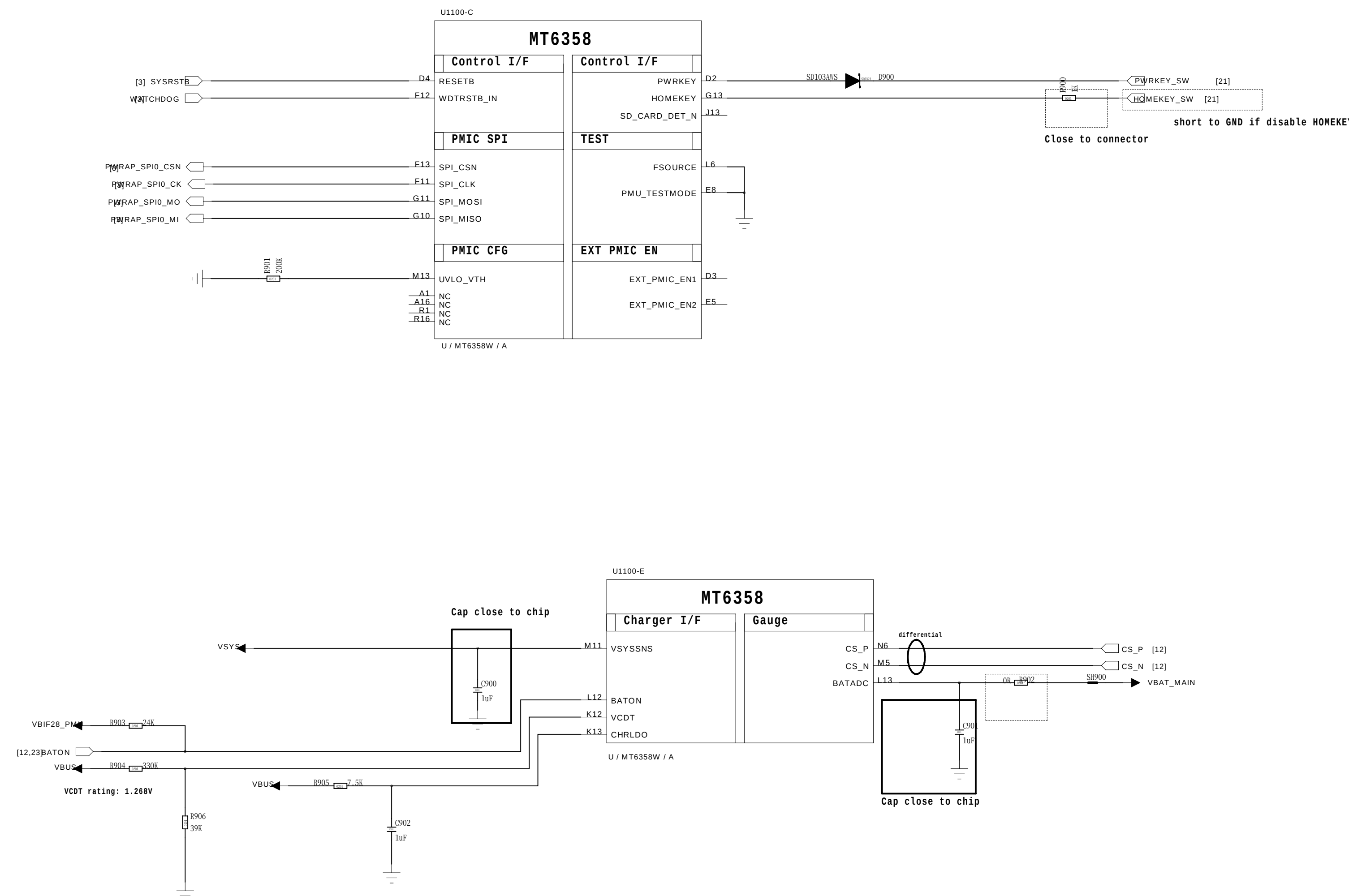
A

D

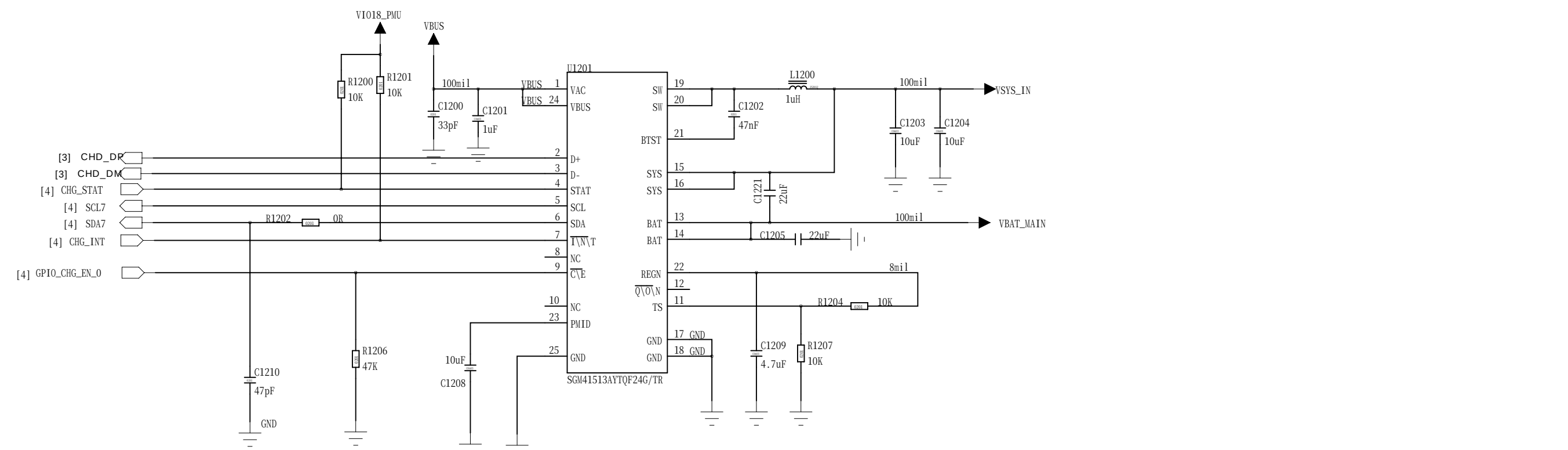
C

B

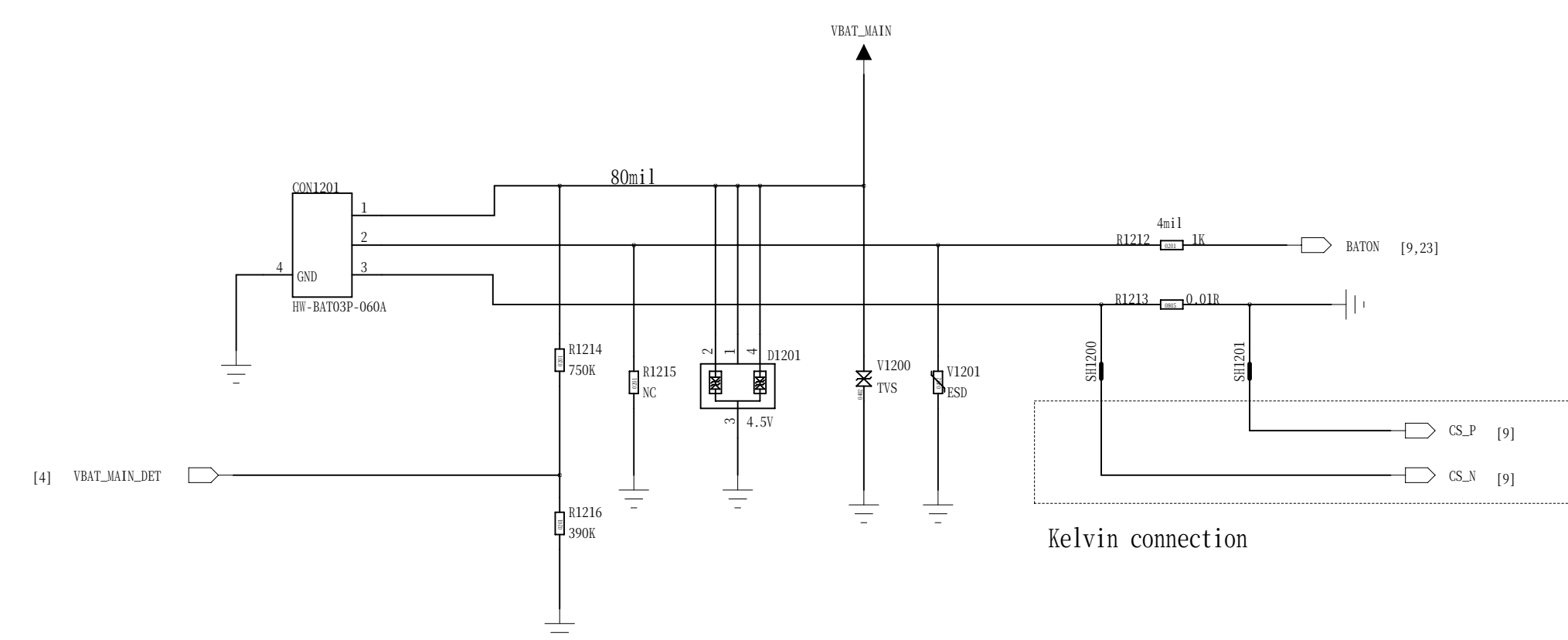
A



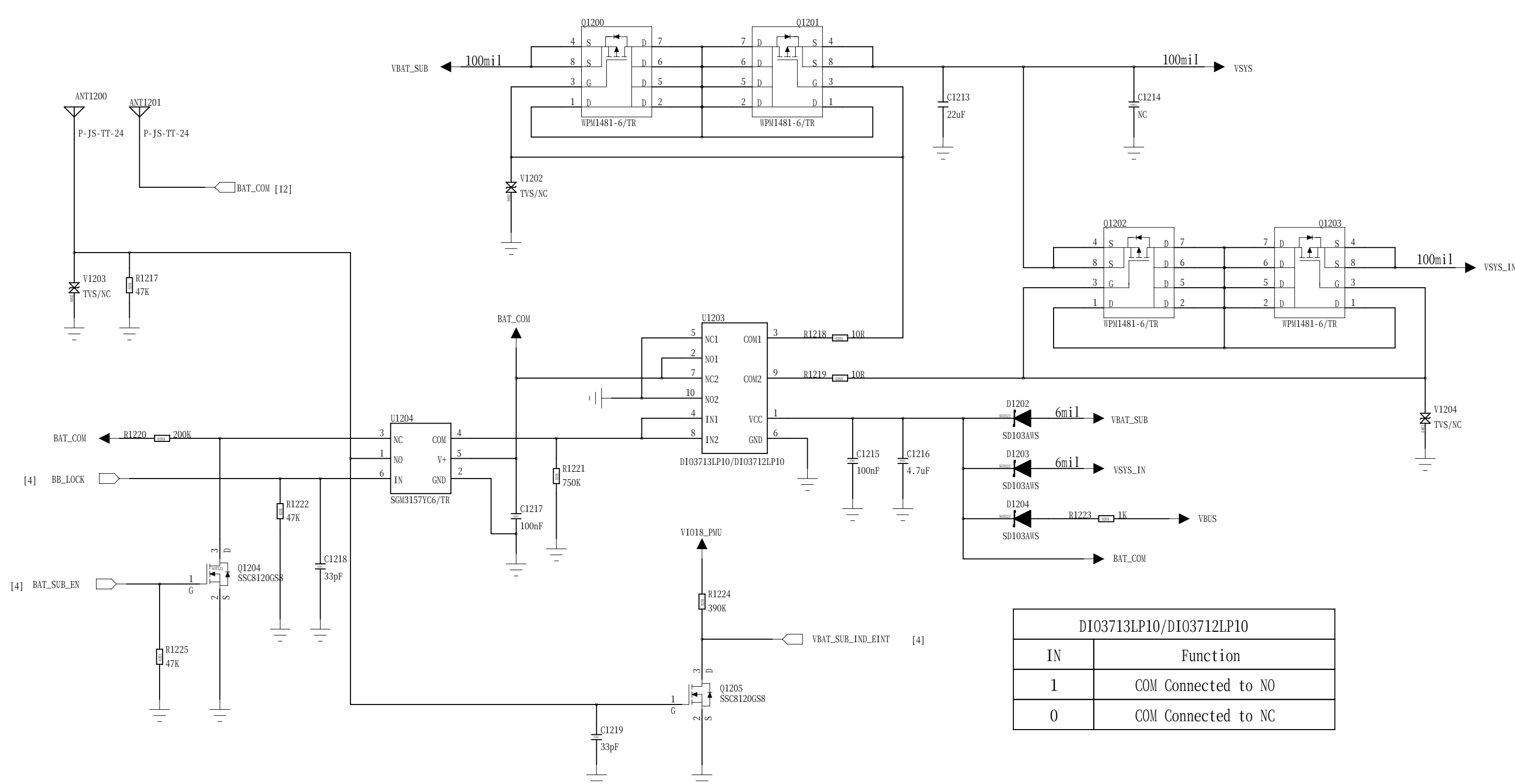
SW Charger



主電池

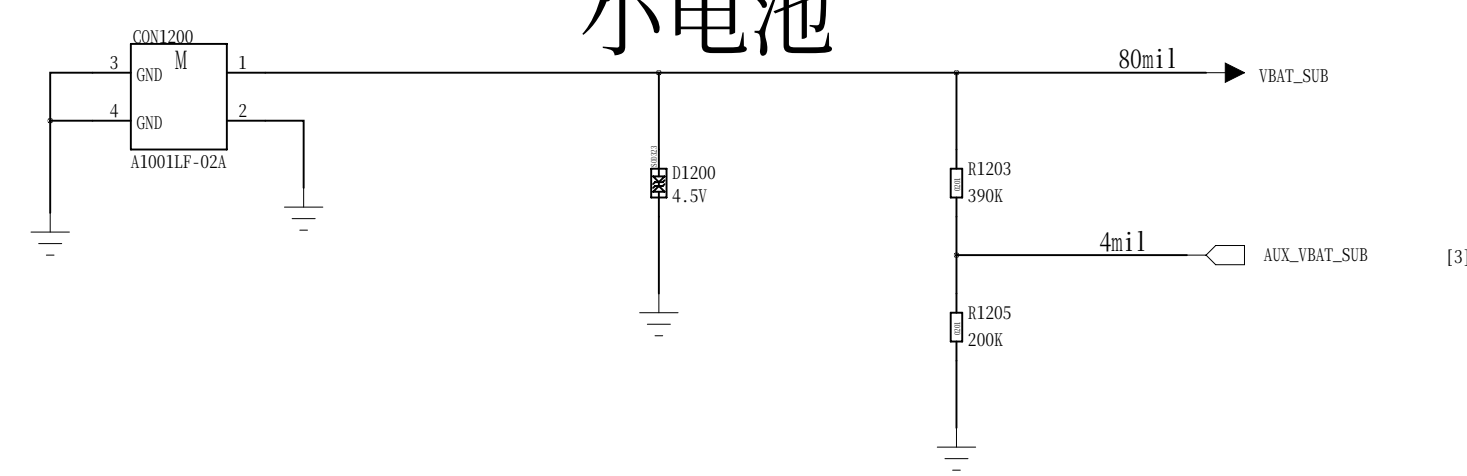


双电池切换

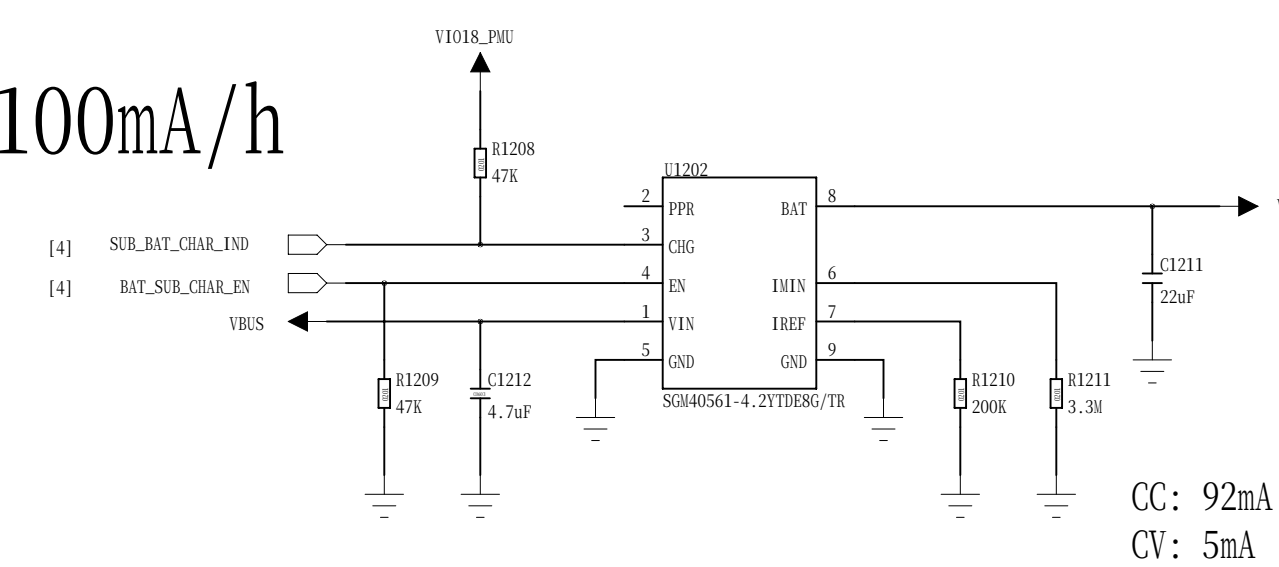


DI03713LP10/DI03712LP10	
IN	Function
1	COM Connected to NO
0	COM Connected to NC

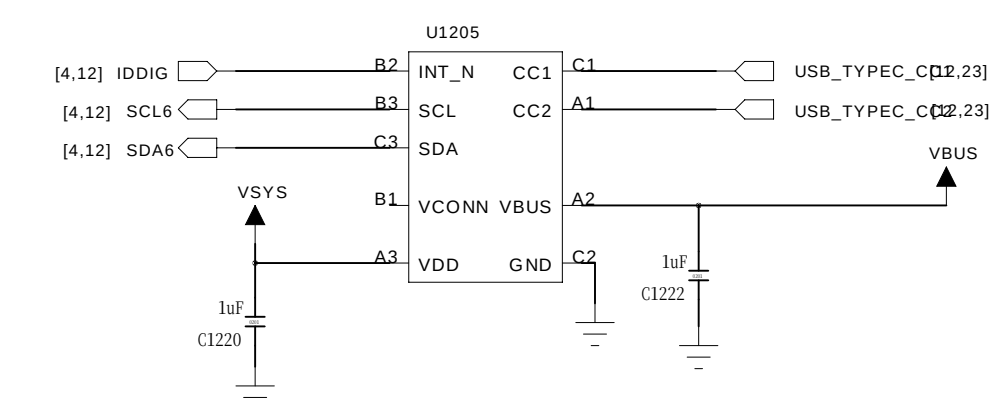
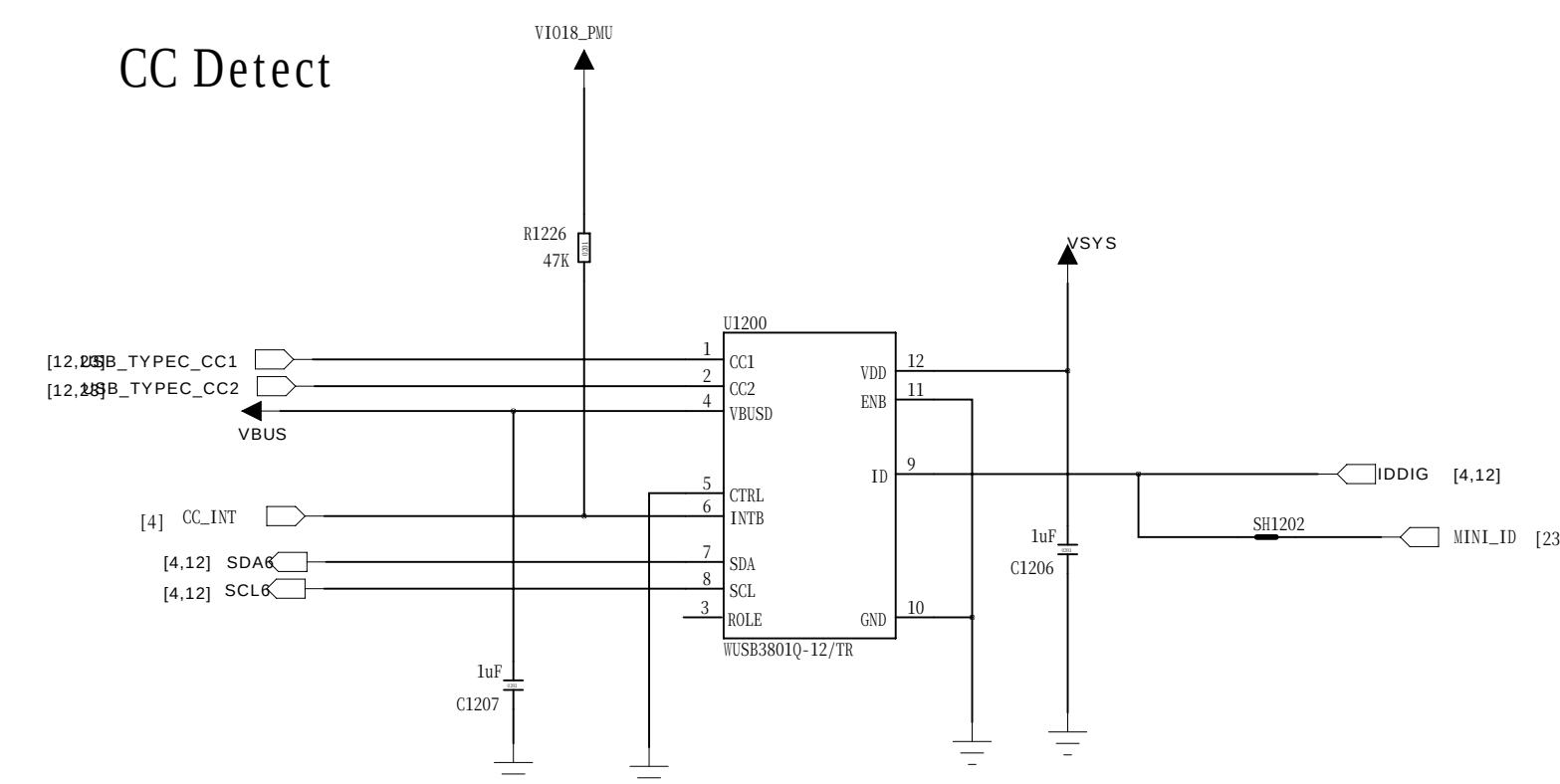
小電池



容量100mA/h



CC Detect



D

C

B

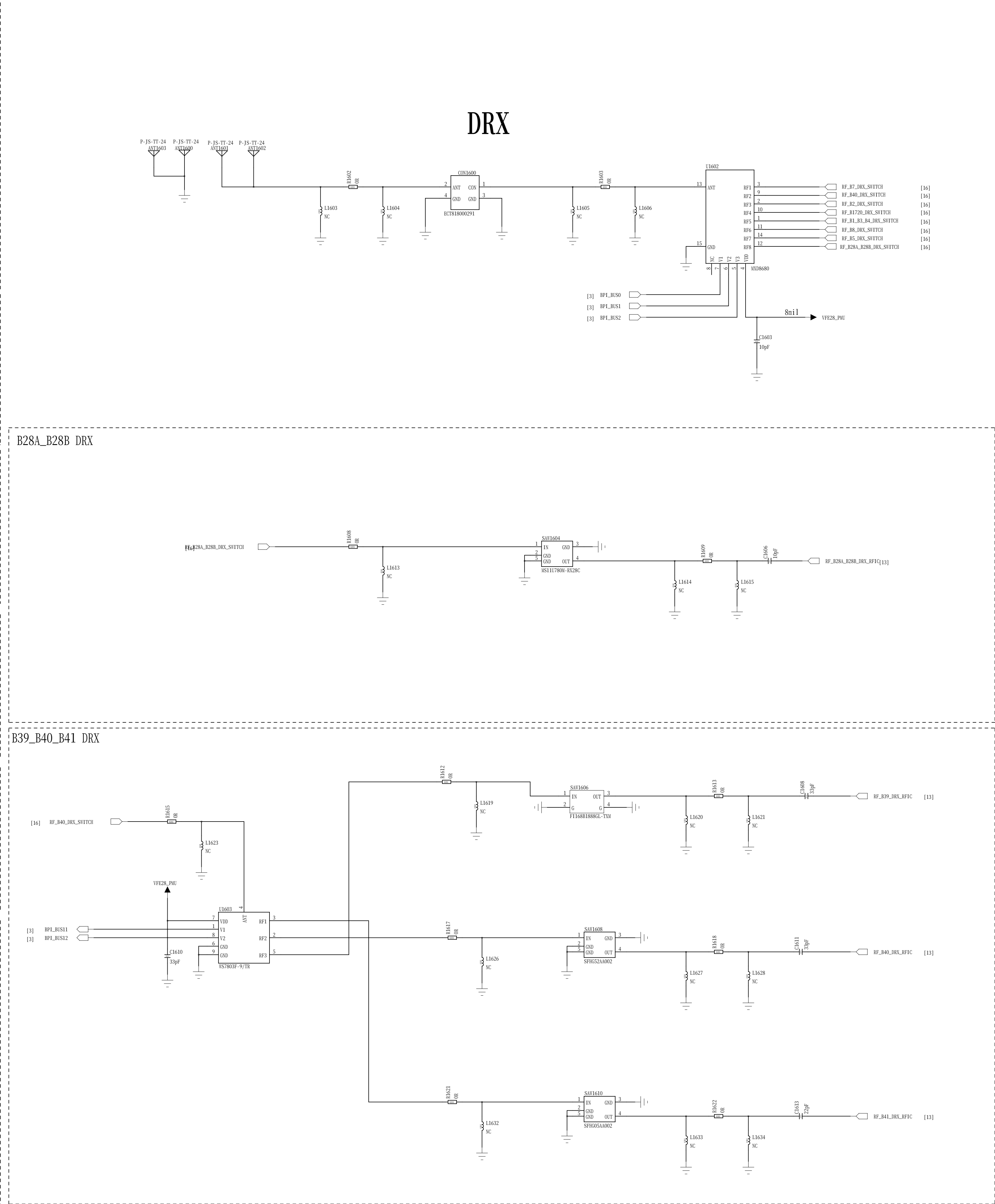
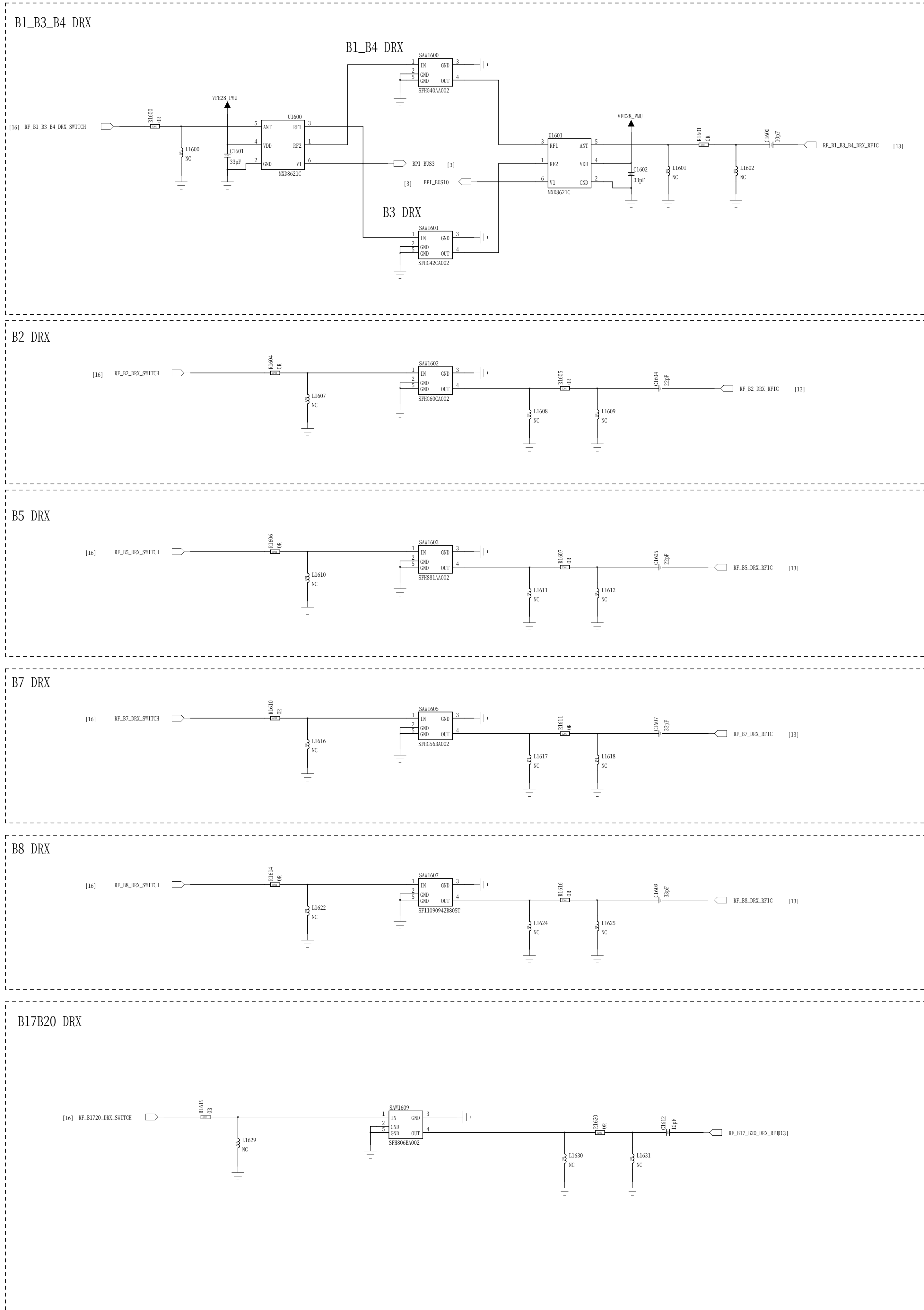
A

D

C

B

A



D

D

C

C

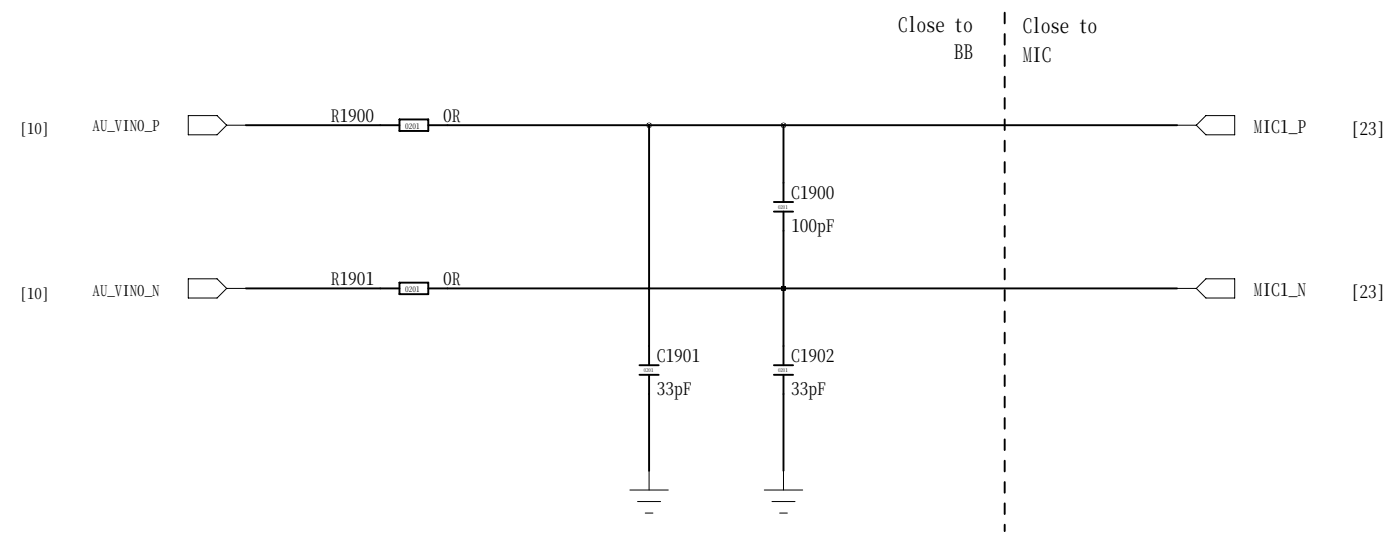
B

B

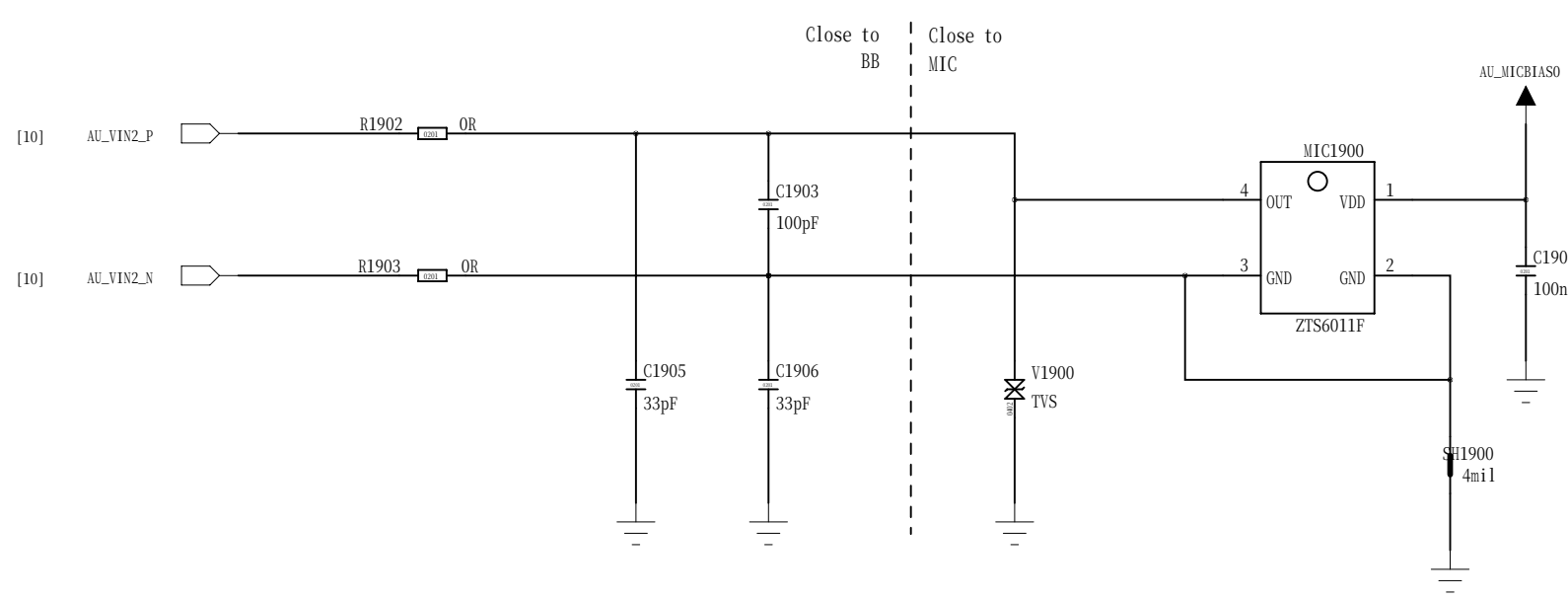
A

A

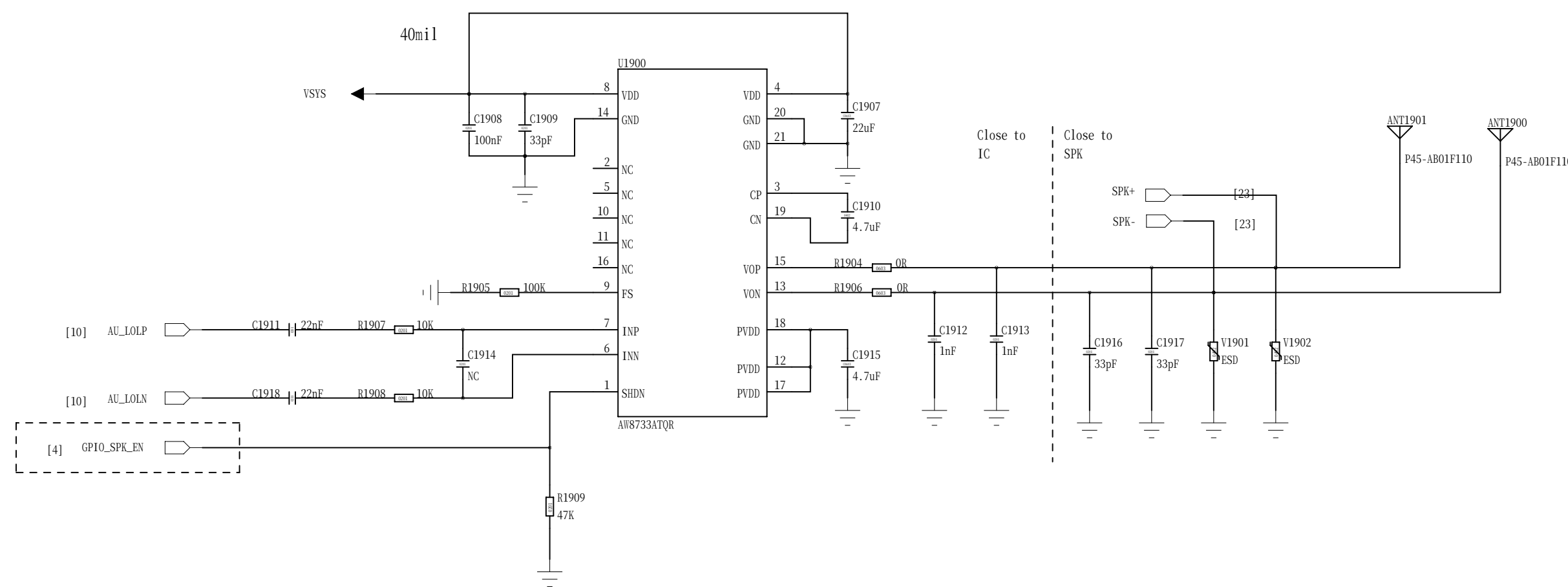
Handset 1nd Microphone



Handset 2nd Microphone

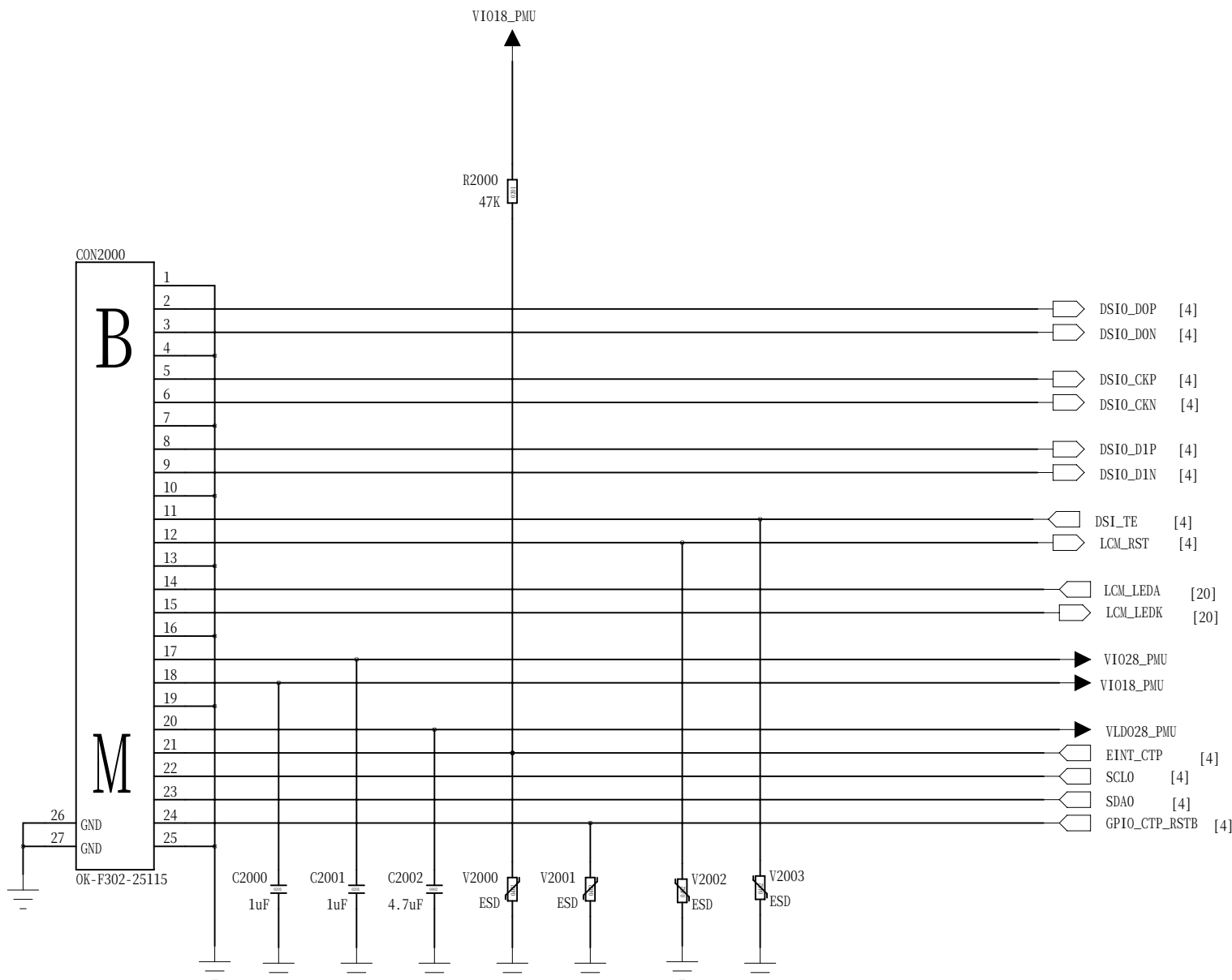


Speaker

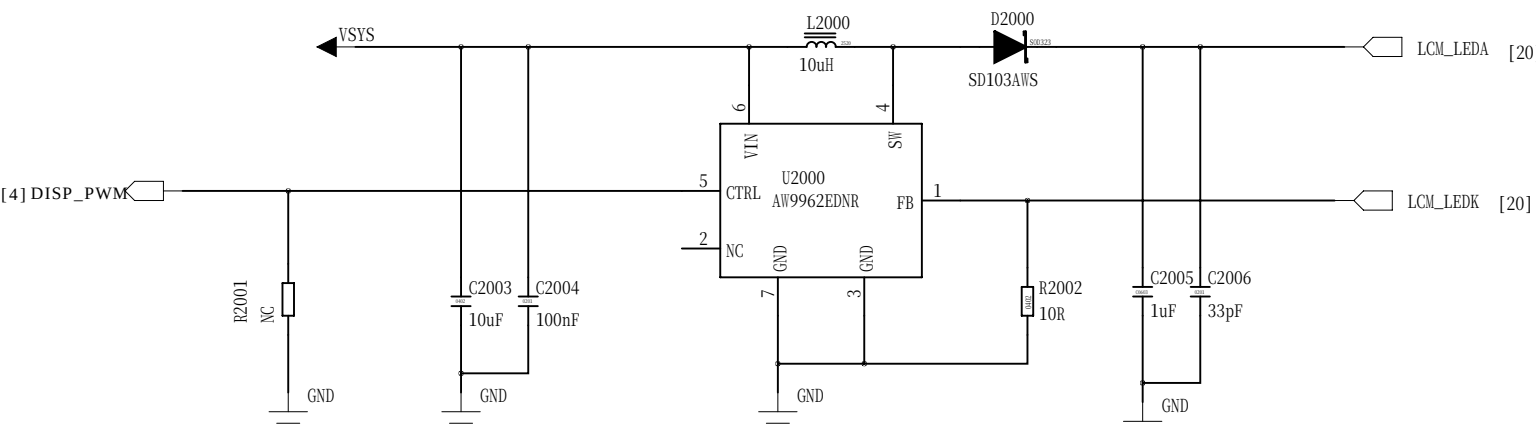


A87519PCR IIC地址										
AD	PIN	B17	B16	B15	B14	B13	A1	A0	B10	读 写
To GND	1	0	1	1	0	0	0	0	0x01	0x00
To SCL	1	0	1	1	0	0	0	1	0x01	0x02
To SDA	1	0	1	1	0	1	0	0	0x01	0x04
To VDD	1	0	1	1	0	1	1	1	0x01	0x06

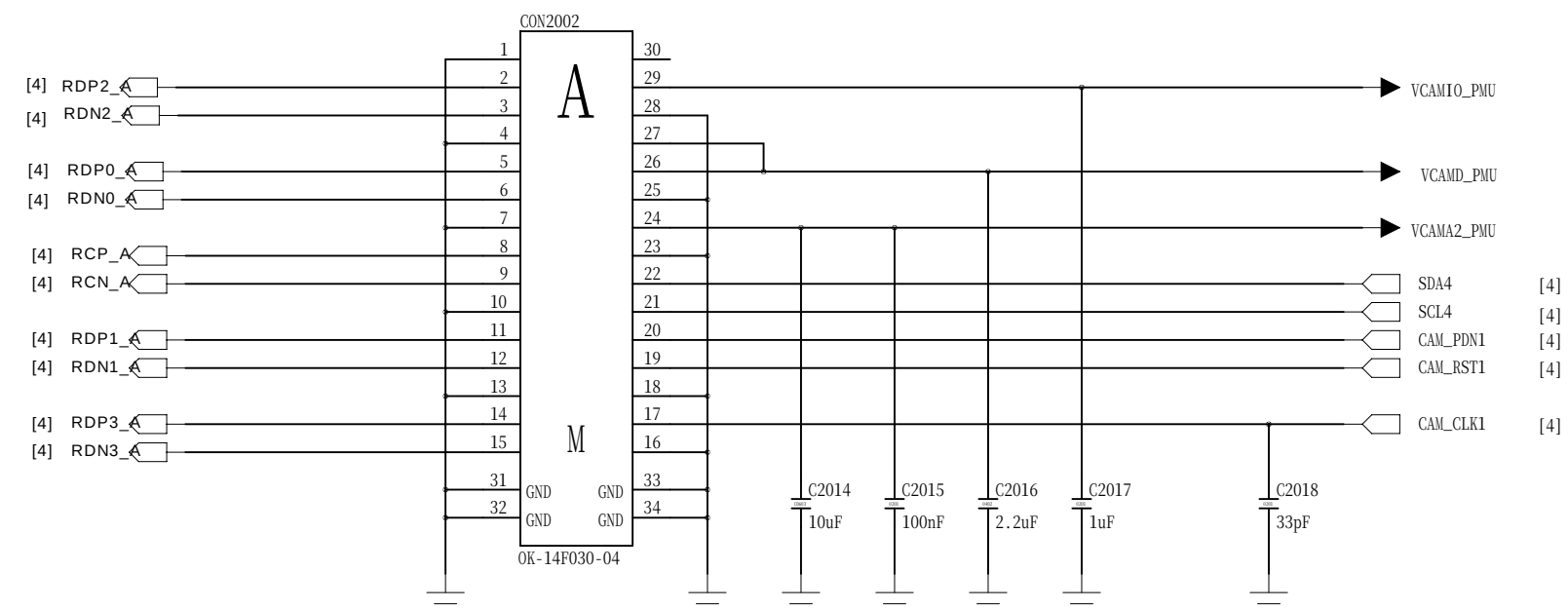
TP + LCD



LCM Backlight LED Driver

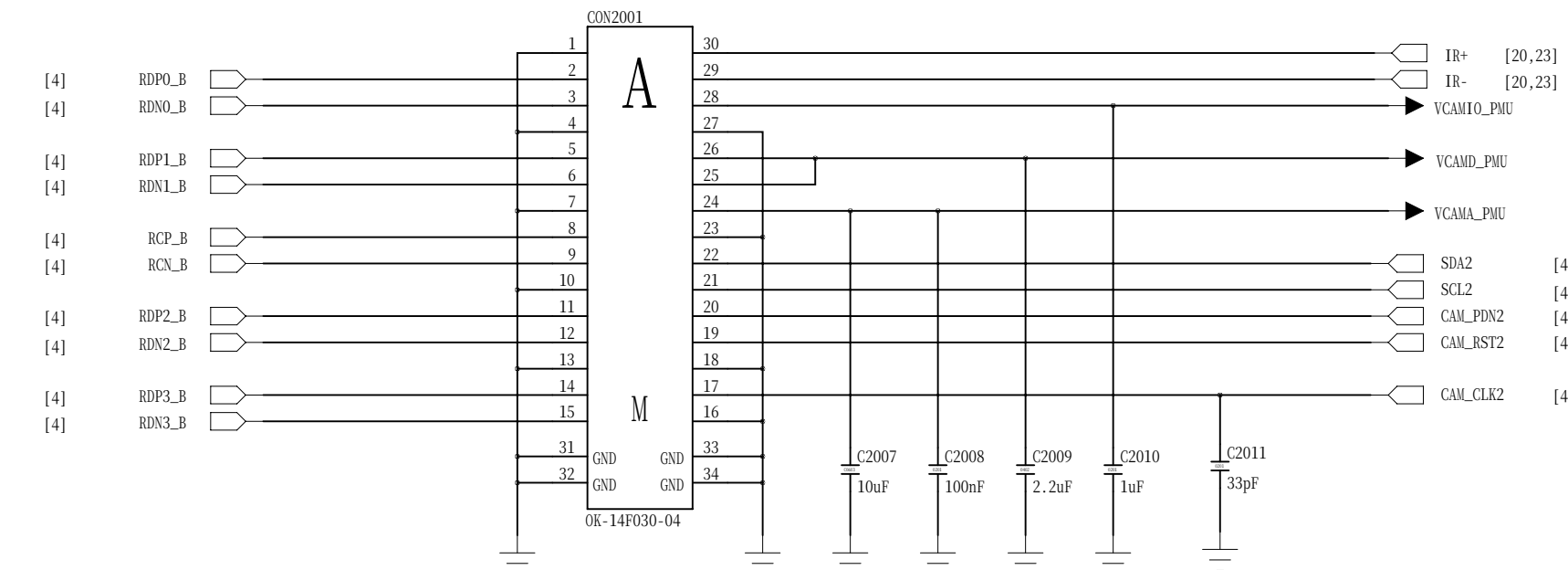


Front camera

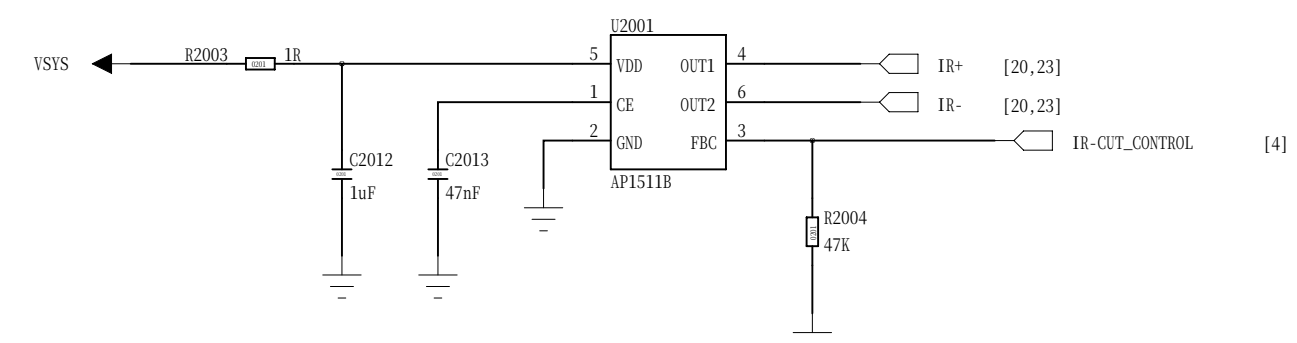


副后掇

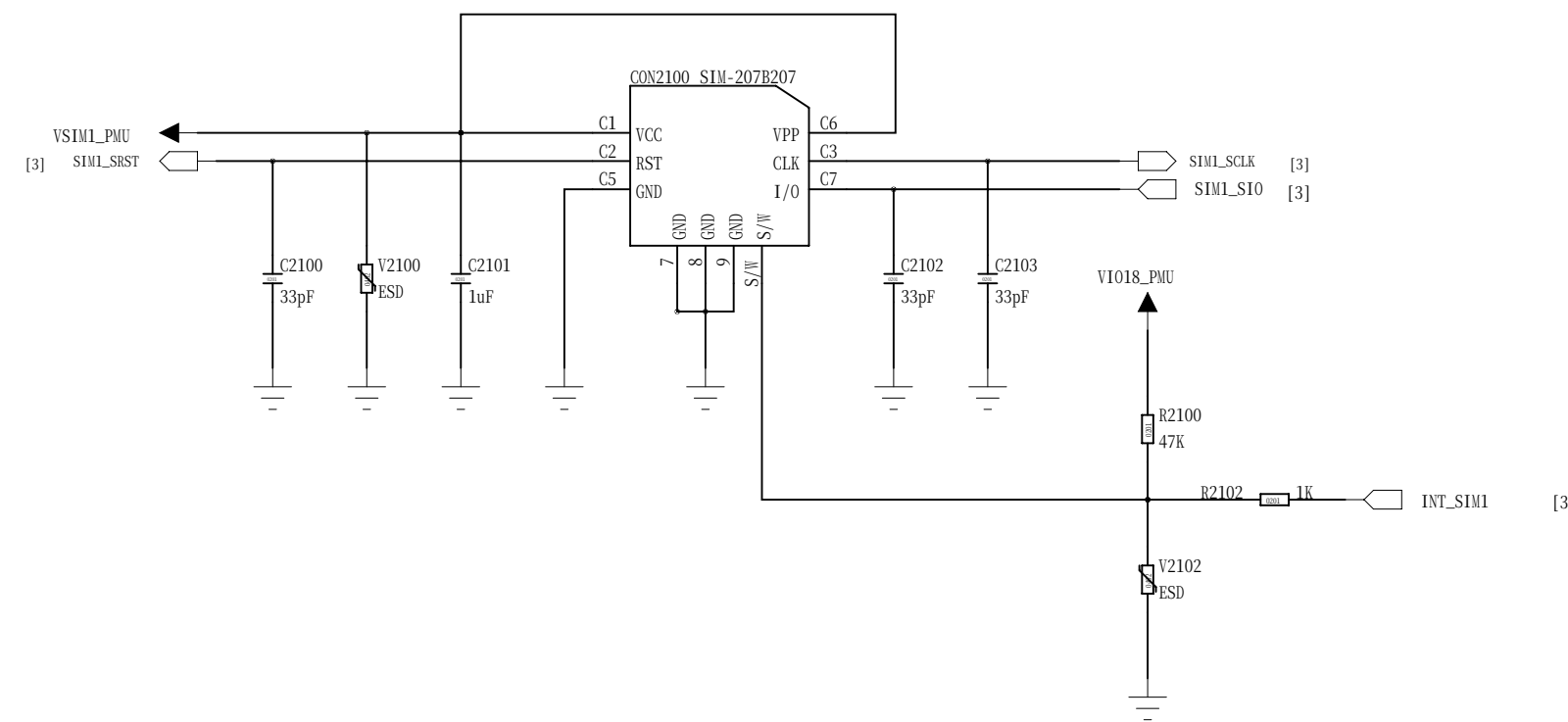
主后撮



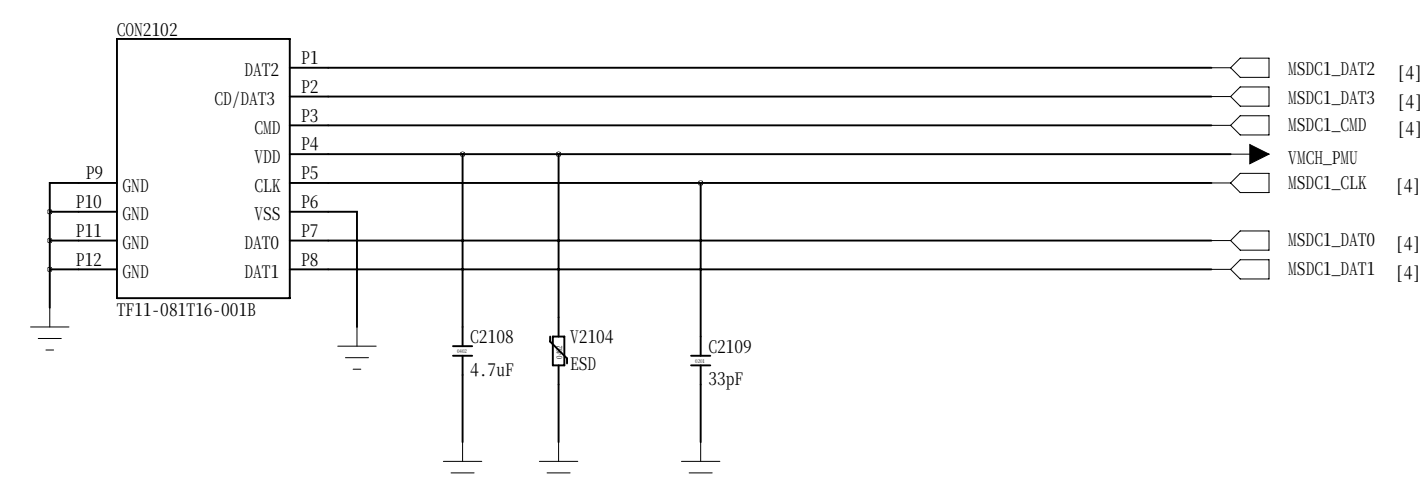
IR - CUT



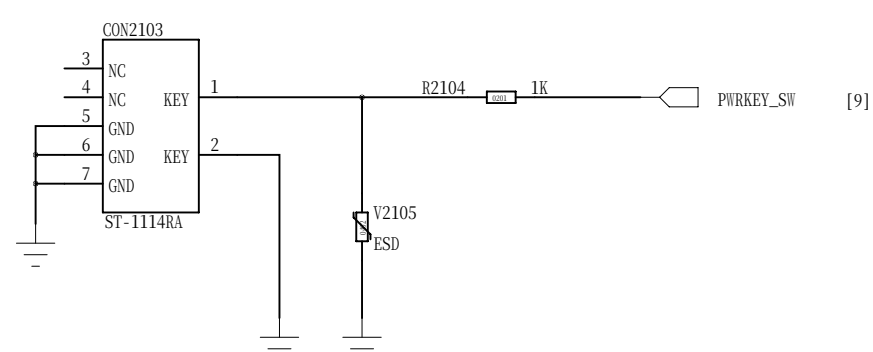
SIM 座



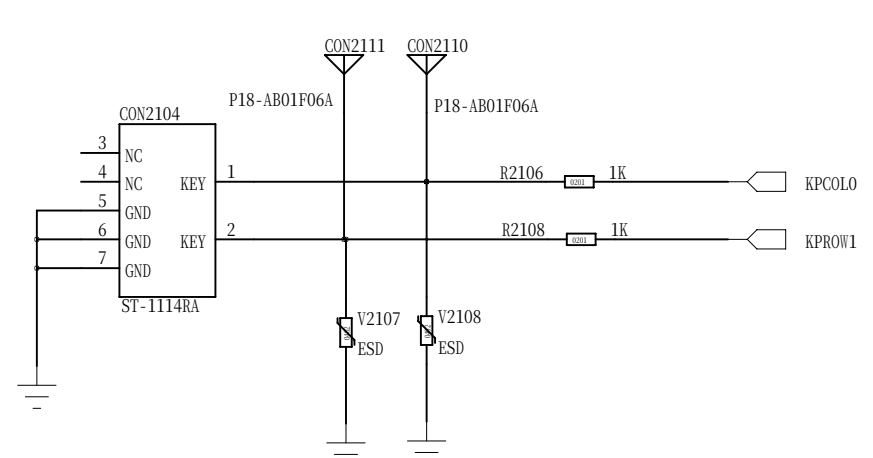
TF 连接器



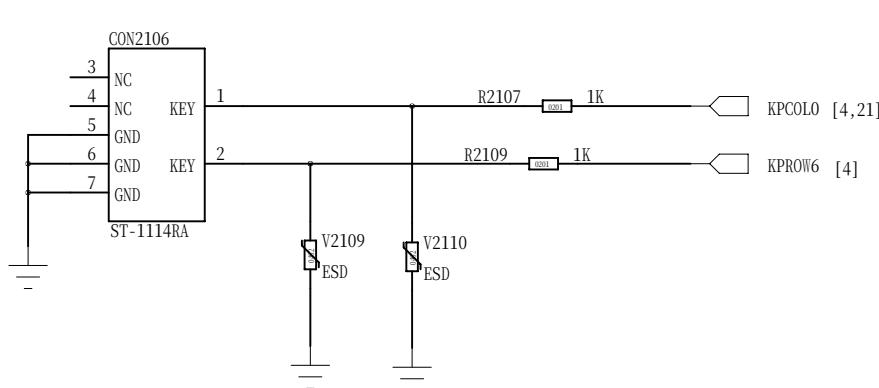
开机键



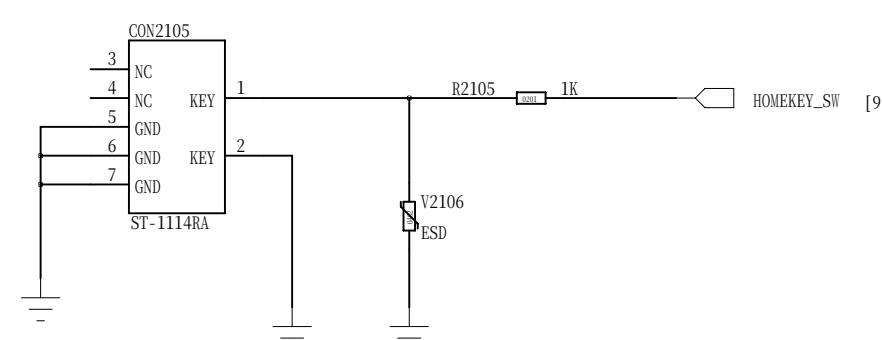
PTT



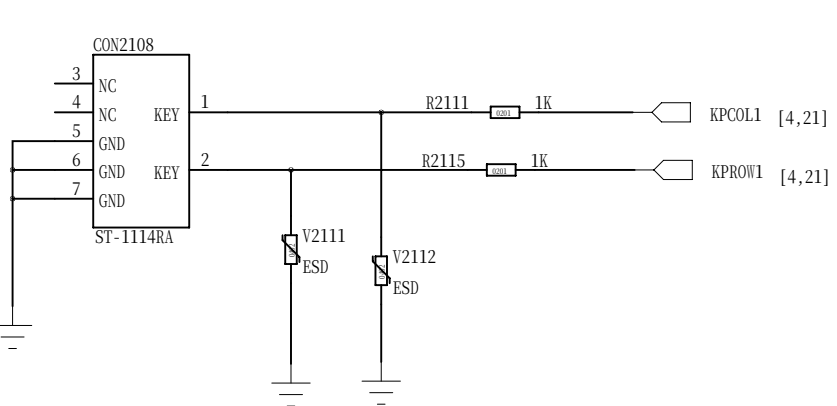
拍照键



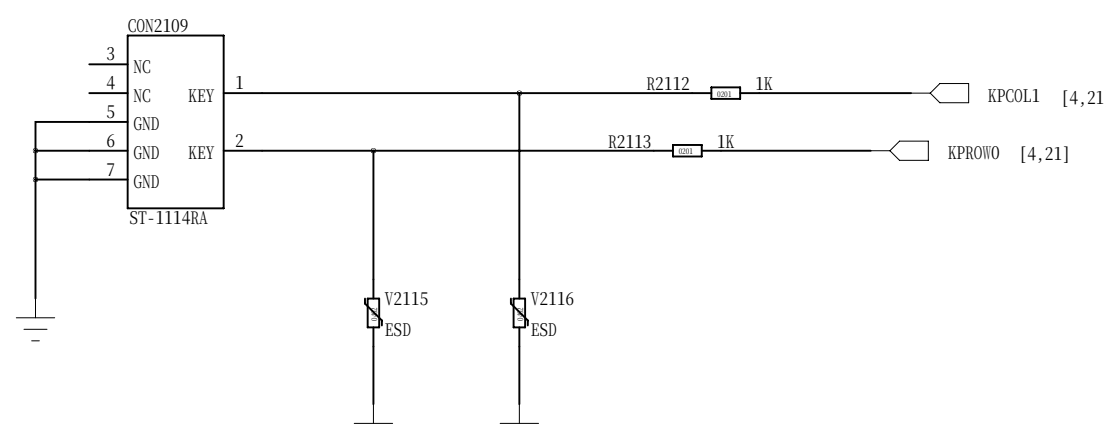
录像键



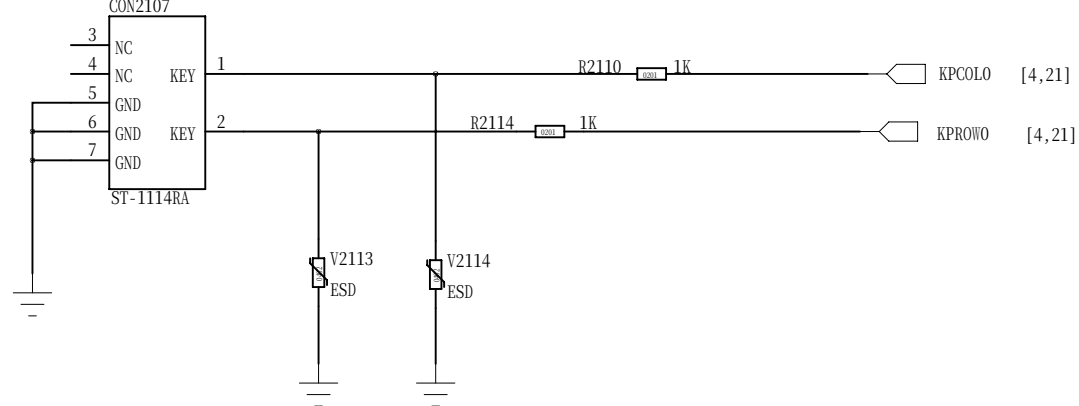
静音键



SOS



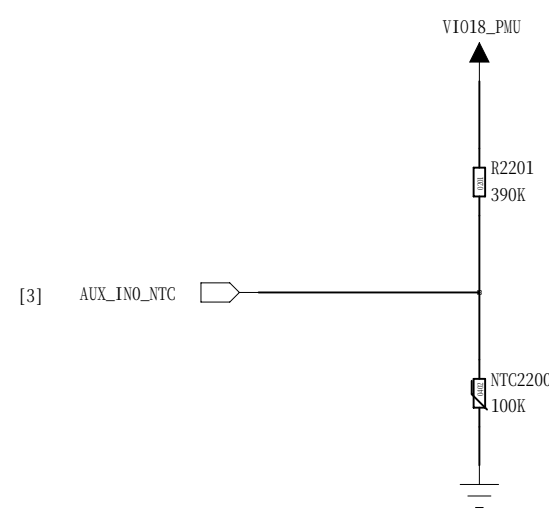
自定义键



Light-sensor

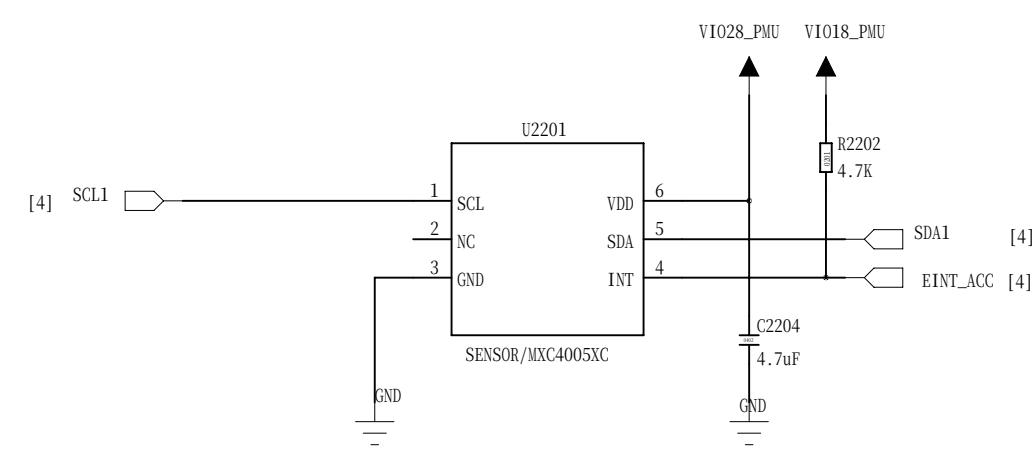
STK321-35A					IIC地址				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	读	写
0	1	0	0	1	0	0	R1/V	0x49	0x48

Thermistor to sense AP Temperature



1. NTC must keep a distance about 6~8 mm away from AP and far from other heat sources 10 mm at least.
2. The distance is the shortest distance from package edge to edge.

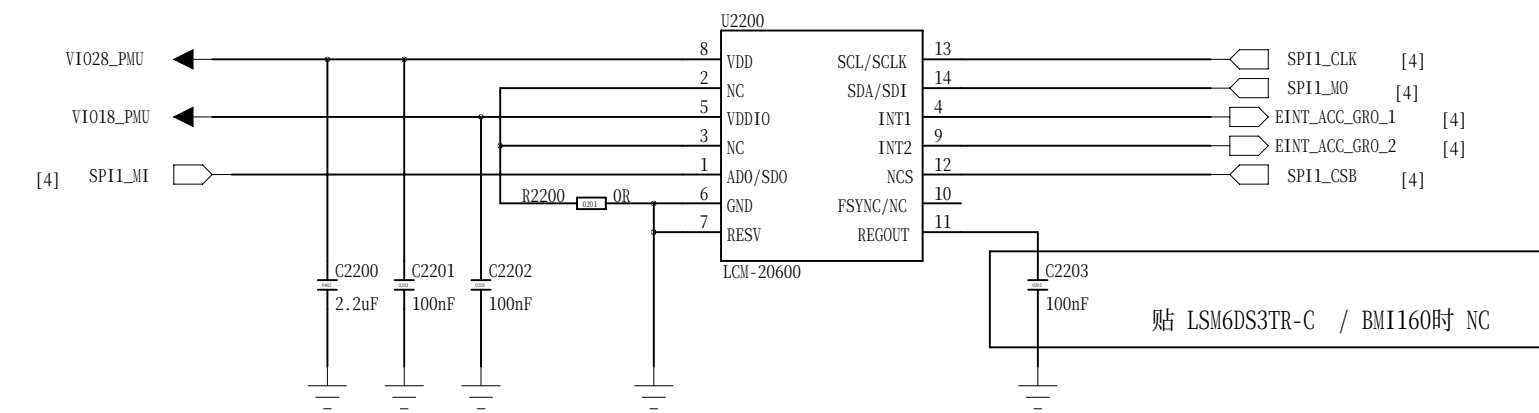
G_SENSOR



ACC + GYRO

摆件注意事项：

1. 距离热源20mm以上, 如CPU、PA、充电IC



LSI60S3TE-C					IIC地址				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	PIN1	Bit0	读	写
1	1	0	1	0	1	0	R1/W	0x05	0xb4
1	1	0	1	0	1	1	R1/W	0xd7	0xb6

ICM-2000					IIC地址				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	PIN1	Bit0	读	写
1	1	0	1	0	0	0	R1/W	0xd1	0xd0
1	1	0	1	0	0	1	R1/W	0xd3	0xd2

COMPASS

摆件注意事项：

1. 距离100mA以上电源线(全层), 保持20mm以上
2. 其它磁性金属材料、电感、IC和天线, 保持15mm以上

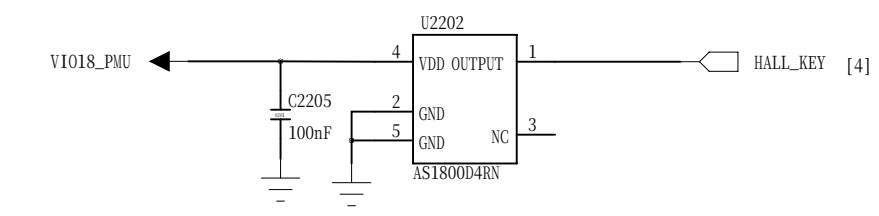
Barometer

AF6133 & AP9133								IIC地址	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	读	写
0	0	0	1	1	0	0	R1/W	0x19	0x18

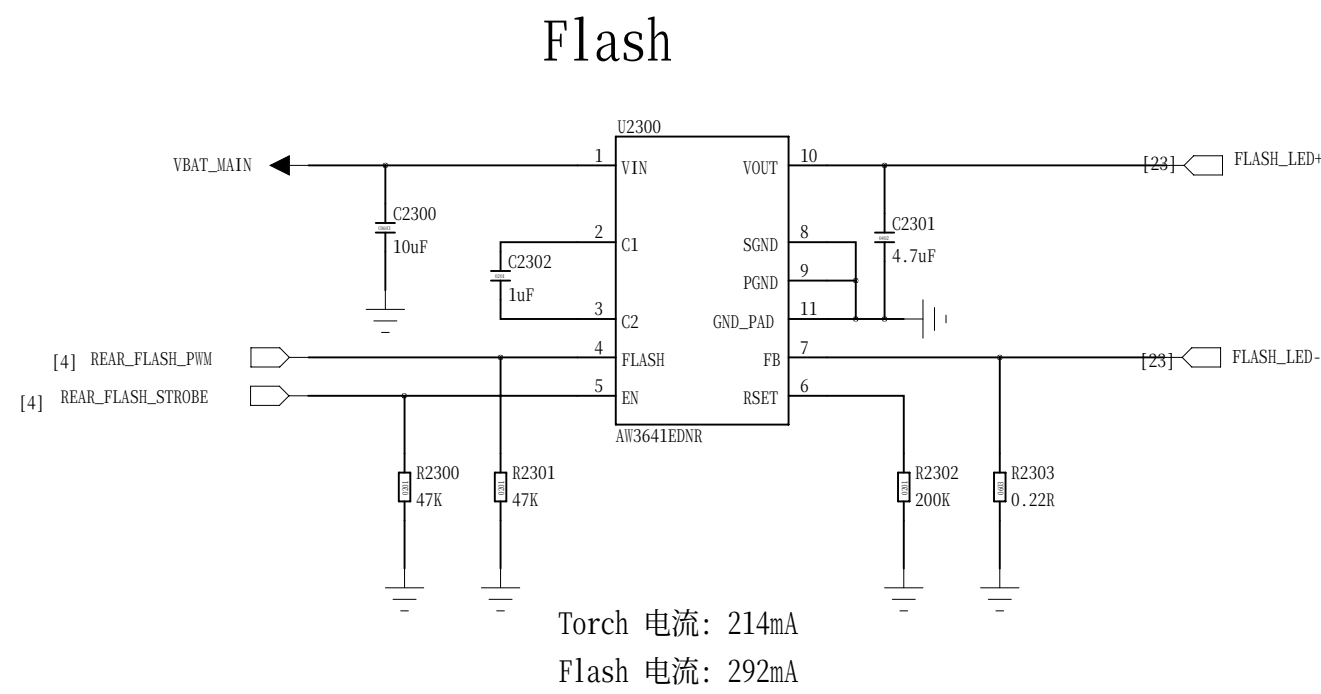
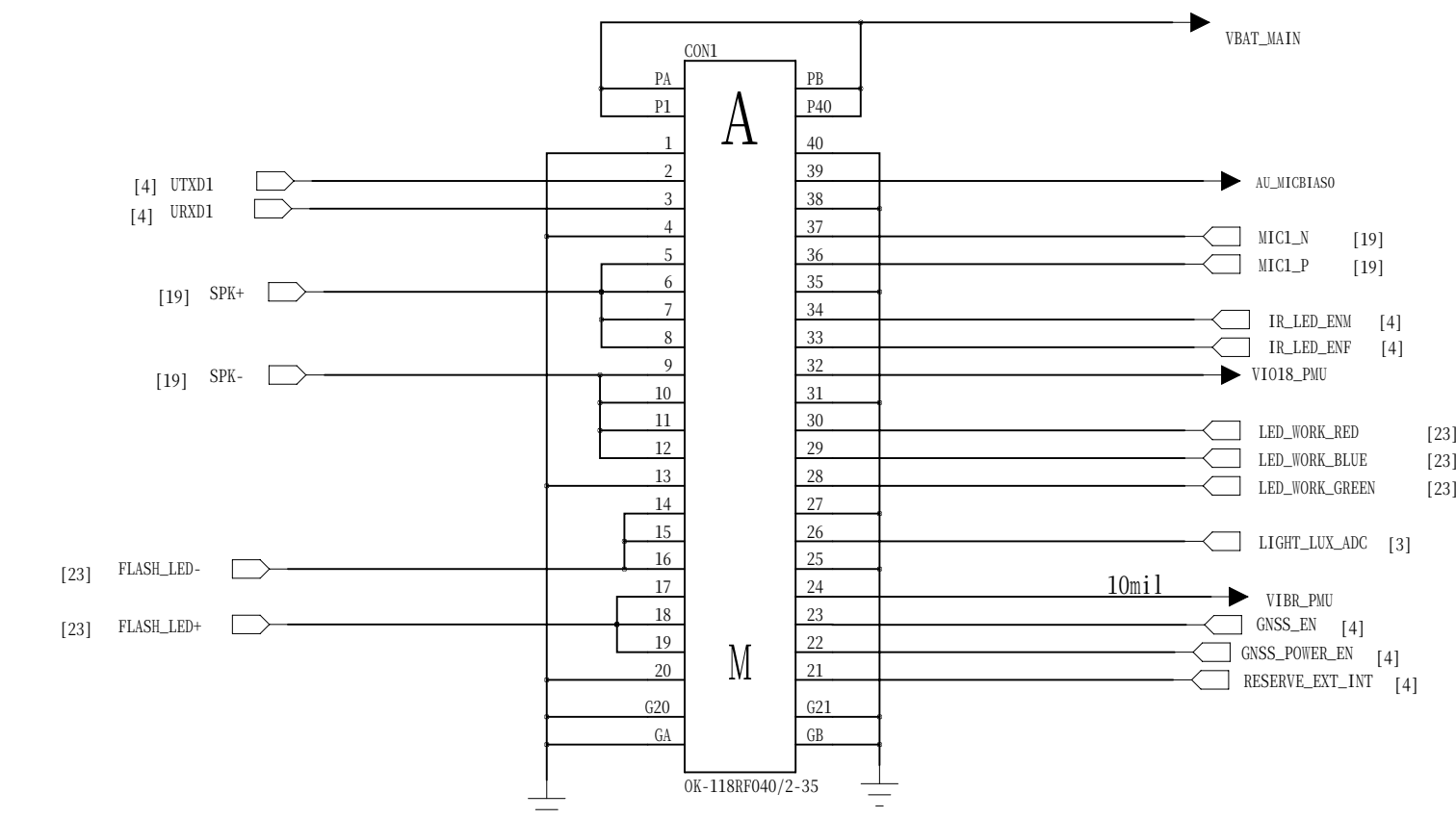
BMF280					IIC地址				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	PIN5	Bit0	读	写
1	1	1	0	1	1	0	R1/W	0xED	0xEC
1	1	1	0	1	1	1	R1/W	0xEF	0xEE

ACCELERATED

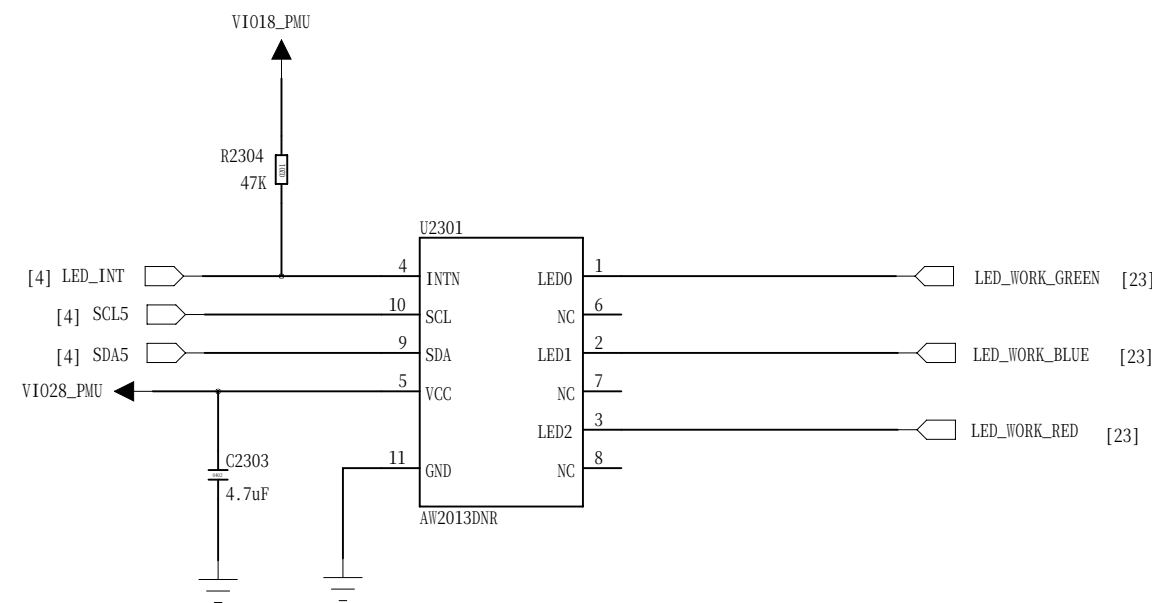
霍尔按键



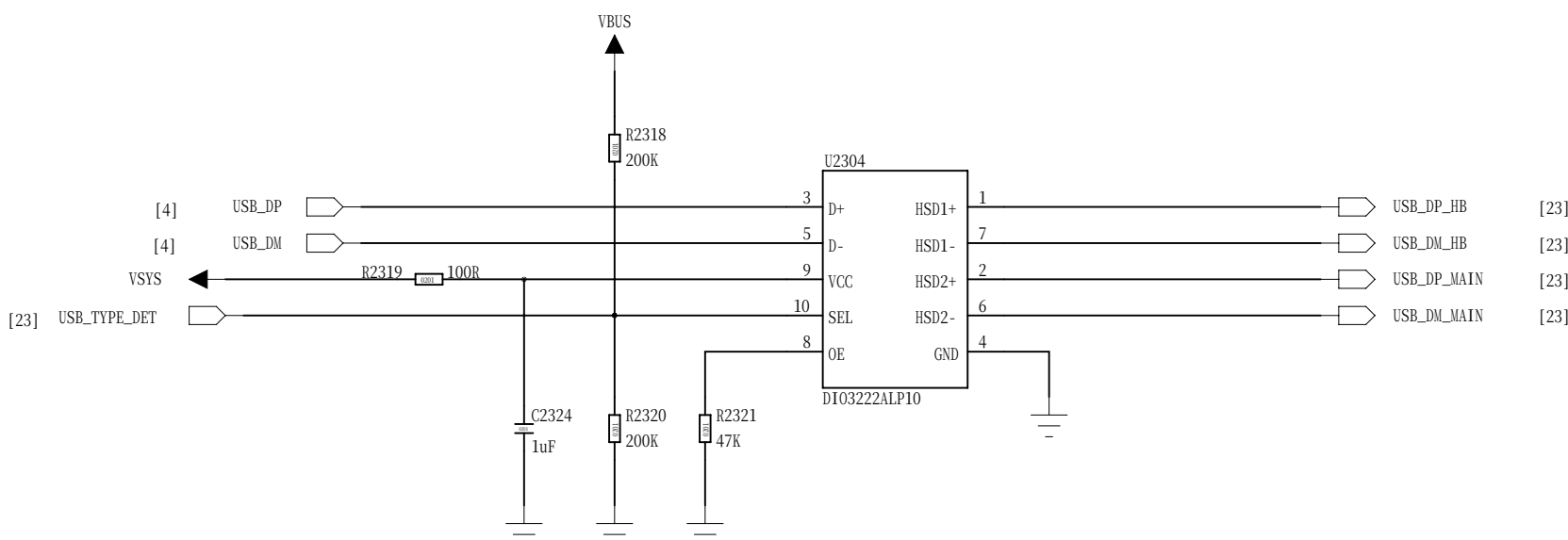
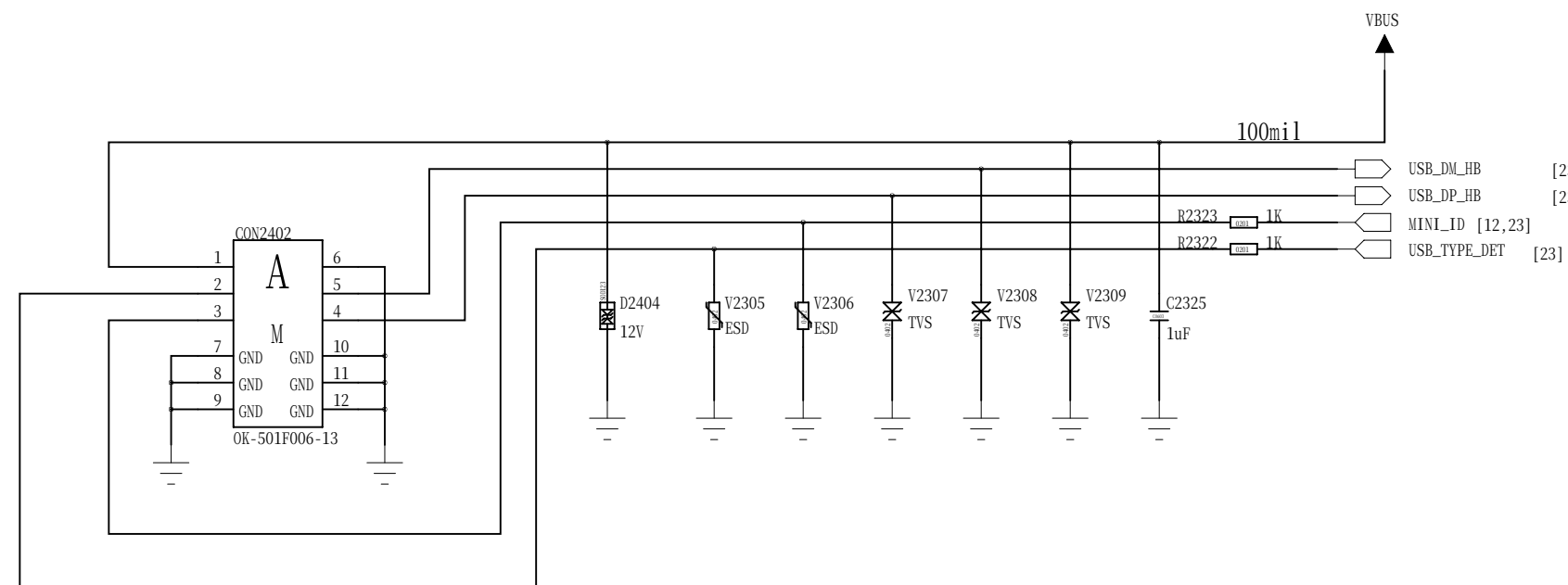
灯板连接器



Torch 电流: 214mA
Flash 电流: 292mA

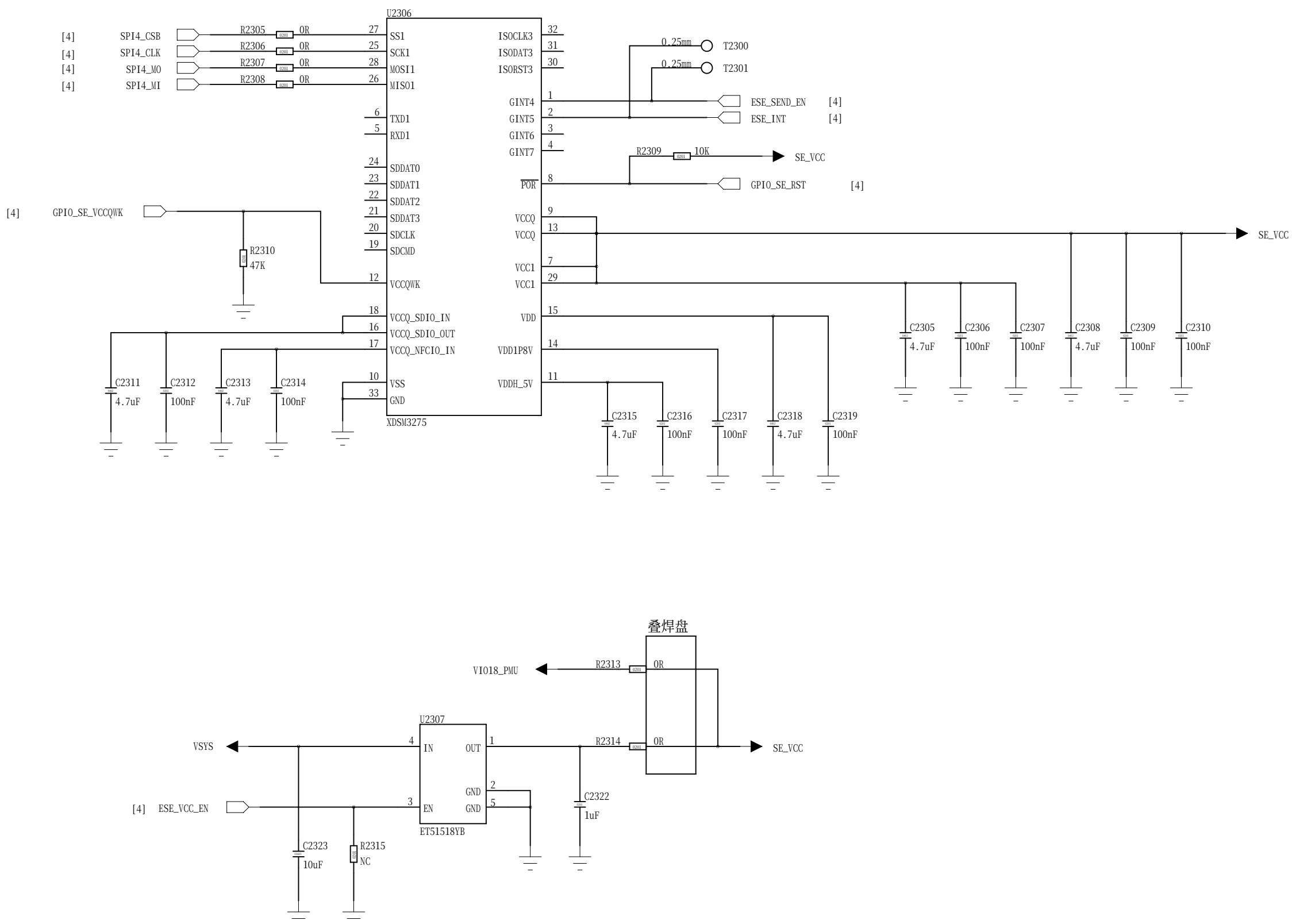


外接磁吸口

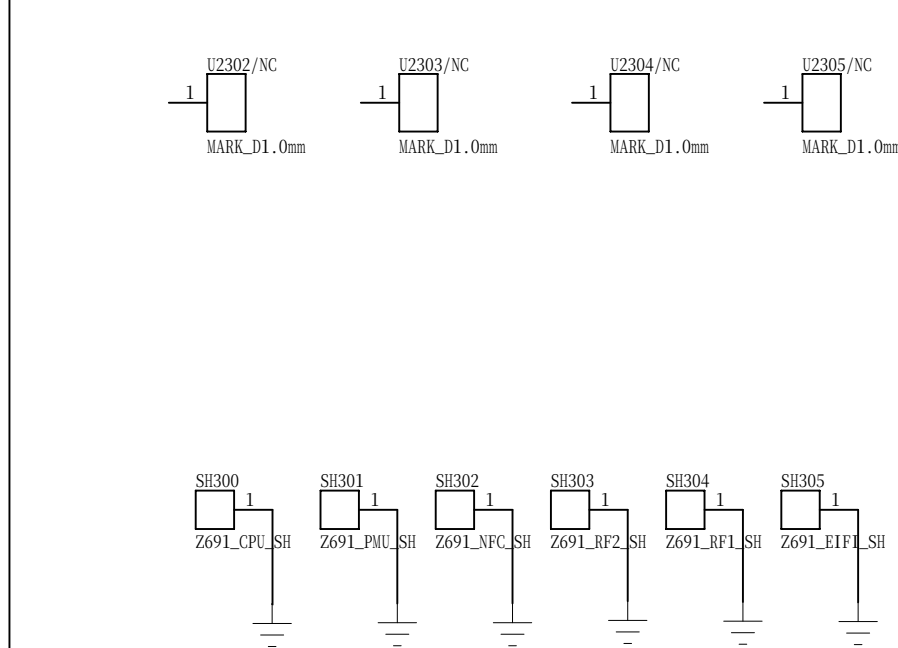
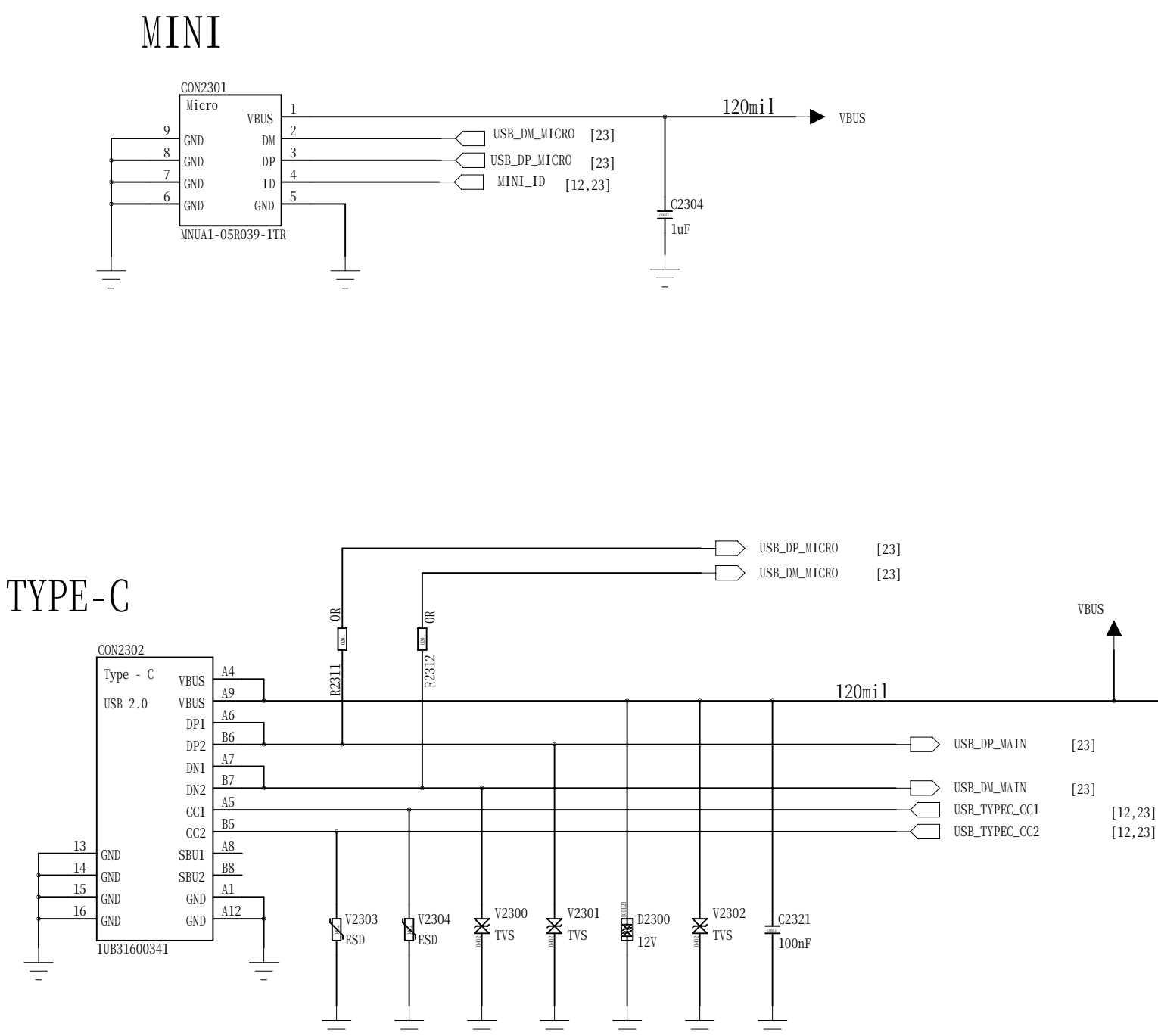


SEL	OE	Function
X	1	Disconnect
0	0	D+, D- = HS01+, HS01-
1	0	D+, D- = HS02+, HS02-

加密芯片



USB连接器



TEST POINT

